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FY2026/6 Business Results

Consolidated Financial Results and Earnings Forecast
Progress of Mid- to Long-Term Management Plan

ULVAC, Inc.

Aug.14 2026

Disclaimer regarding forward-looking statements etc.

■ Forward-looking statements

Forward-looking statements of the company in this presentation are based on information that was available at the time these documents were prepared. There are several factors that directly or indirectly impact the company performance, such as the global economy; market conditions for FPDs, semiconductor, electronic devices, and raw Materials; trends in capital expenditures and fluctuations in exchange rates. Please note that actual business results may differ significantly from these forecasts and future projections.

■ Processing of numbers

Figures and percentages in this document have been rounded to the nearest unit.

■ Product Category Change

From FY25/6, the name of “FPD production equipment” has been changed to “Display and Energy-Related Production Equipment”.

1. FY2026/6 Financial Results Overview

- Orders received: **Achieved a record high of ¥324.2 billion**, driven by Semiconductor, Display, and Rare earth-related businesses.
- Net sales and Operating profit: Exceeded previous forecast, but resulted in higher sales and lower profit YoY due to the recording of one-time EV-related expenses, etc.

2. FY2027/6 Financial Forecast

- Orders received and Net sales: Despite factoring in a drop-off due to business reforms activities and a reactionary decline in Display-related sectors, the Semiconductor and electronics business is expected to continue at a high level.
- Each profit item: Due to the contribution of highly profitable projects such as Semiconductor and Rare earth-related businesses, the Gross profit margin is expected to **reach the Value-up Plan level (33.7%)**, with a significant improvement in the Operating profit margin as well.

3. Progress of the Mid- to Long-Term Management Plan (Value-up Plan)

In response to changes in the business environment, we are conducting a "comprehensive review and transformation" of the Value-up Plan during FY2027/6, leading to profit growth in FY2028/6 and onward.

- Growth strategy: Define AI・Data center-related businesses as strategic themes, concentrating management resources into these priority areas.
- Business reform: Redefine head office functions, the fixed cost structure, and business portfolio reforms to accelerate business transformation
- Production reform: Maximize sales and profit, promote the early resolution of material supply and production constraints as a top priority.

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FY2026/6 Financial Results Overview

Financial Results Overview

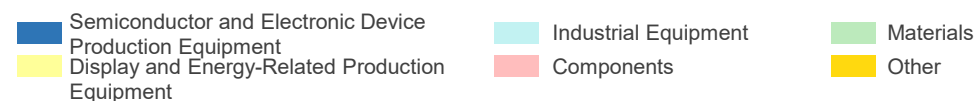
- Orders received: Achieved a record high of ¥324.2 billion, a significant increase of ¥98.7 billion YoY.
- Net sales: Landed roughly in line with previous forecasts, an increase in sales of ¥17.9 billion YoY.
- Each profit item: Landed roughly in line with previous forecasts mainly due to the recording of one-time EV-related expenses.

(Unit: ¥1 billion)	FY25/6	FY26/6					
		Previous Forecast	Full Year Forecast	YoY		Vs.Previous Forecast	
Orders Received	225.6	310.0	324.2	+98.7	+44%	+14.2	+5%
Net Sales	251.2	260.0	269.1	+17.9	+7%	+9.1	+4%
Gross Profit	79.9	77.0	77.7	-2.1	-3%	+0.7	+1%
Gross Profit Margin	31.8%	29.6%	28.9%	-2.9pt	-	-0.7pt	-
Operating Profit	26.5	19.0	19.6	-6.9	-26%	+0.6	+3%
Operating Profit Margin	10.6%	7.3%	7.3%	-3.3pt	-	0.0pt	-
Profit attributable to owners of parent	16.7	18.5	17.1	+0.4	+2%	-1.4	-8%
To net sales ratio	6.6%	7.1%	6.4%	-0.3pt	-	-0.8pt	-
Dividend per share(Yen)	164	152	152	-12	-	±0	-

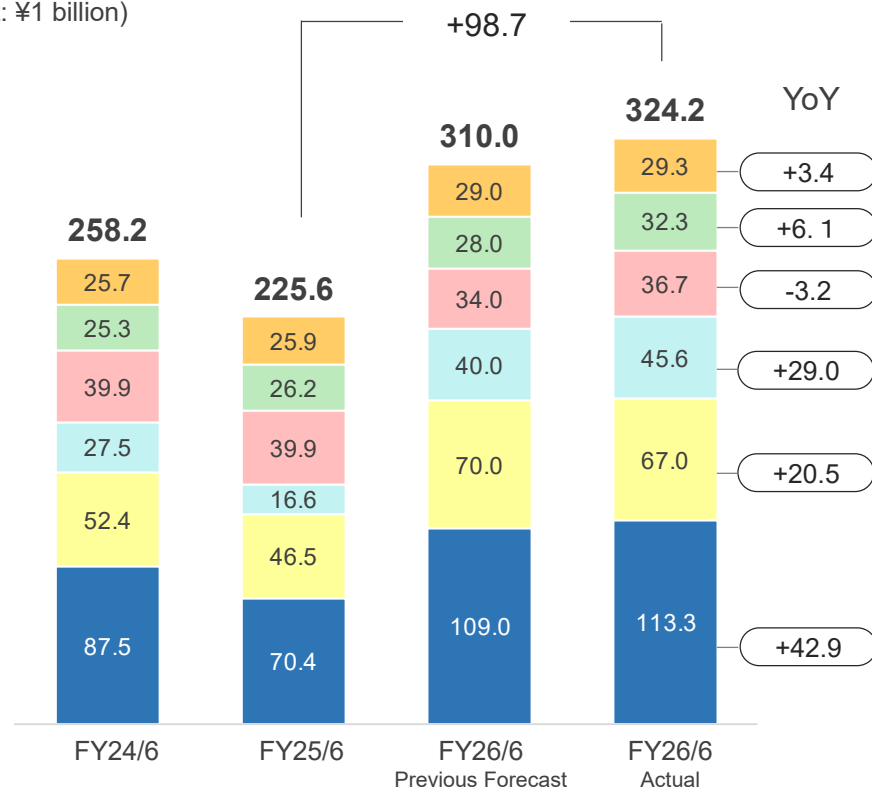
Orders Received and Net Sales Results

- Orders received: Achieved a record high, with significant YoY increases in Semiconductor, Display and General industries including the Rare earth-related businesses.
- Net sales: Landed roughly in line with previous forecast.

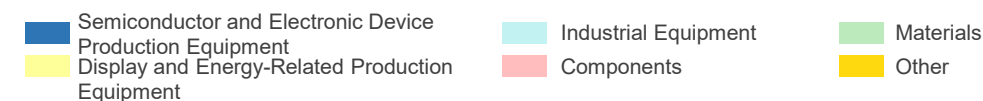
Orders Received



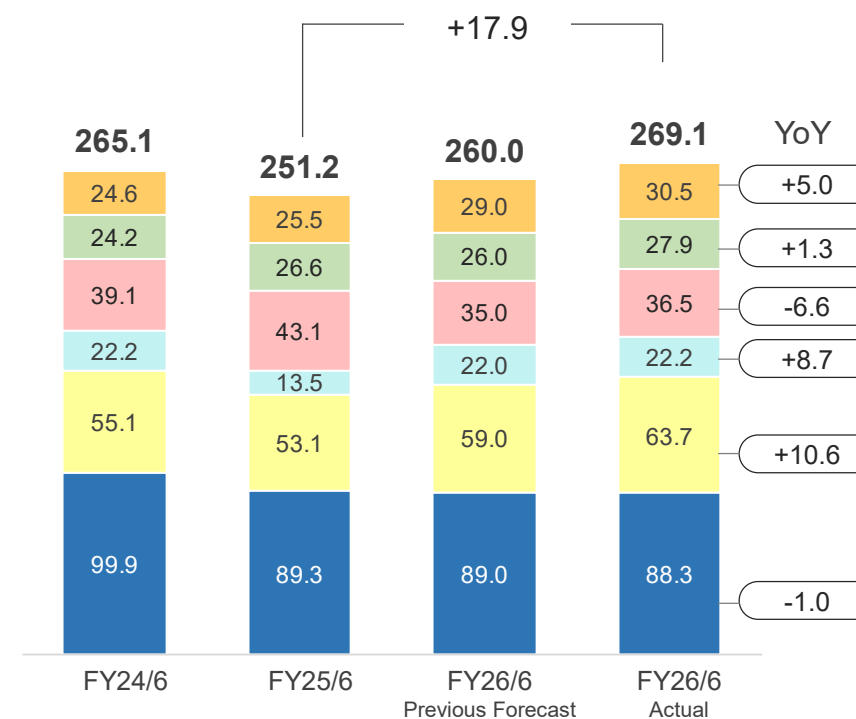
(Unit: ¥1 billion)



Net Sales



(Unit: ¥1 billion)



※ From FY26/6, leak test systems have been reclassified from the Components segment to the Industrial Equipment segment for both orders received and sales

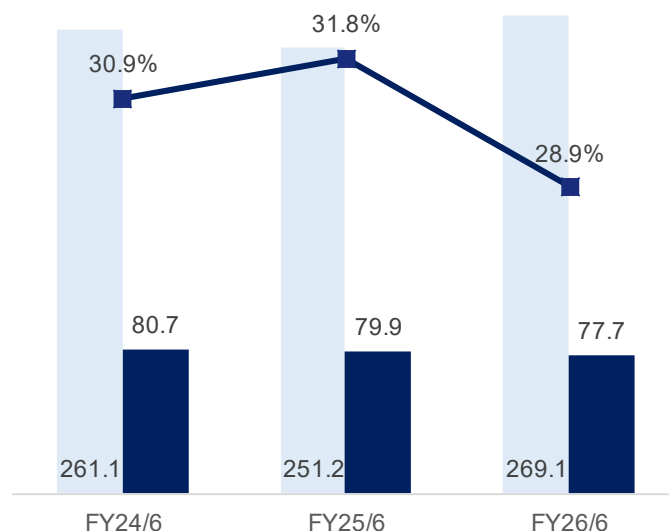
Profit Margin Trends

- Gross profit margin: Decreased by 2.9 pt YoY, due to the recognition of EV-related expenses, mix changes from an increase in display-related businesses, etc.
- Operating profit margin: Decreased by 3.3 pt YoY due to an increase in SG&A expenses driven by one-time factors, higher R&D expenses, etc.

(Unit: ¥1 billion, %)

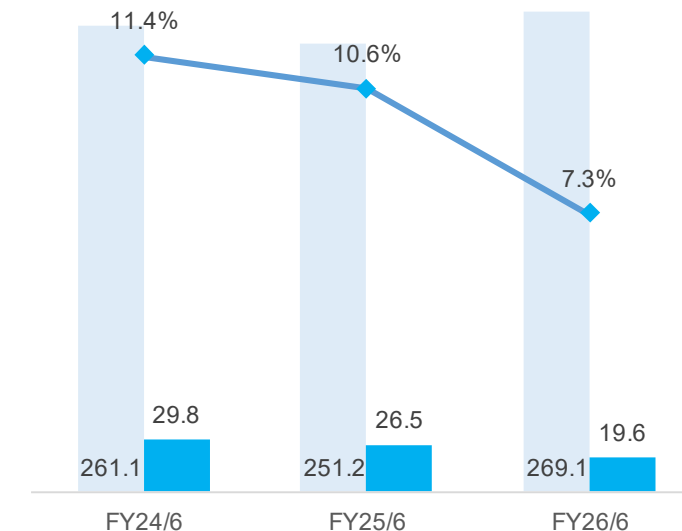
Gross Profit Margin

Net Sales Gross Profit Gross Profit Margin



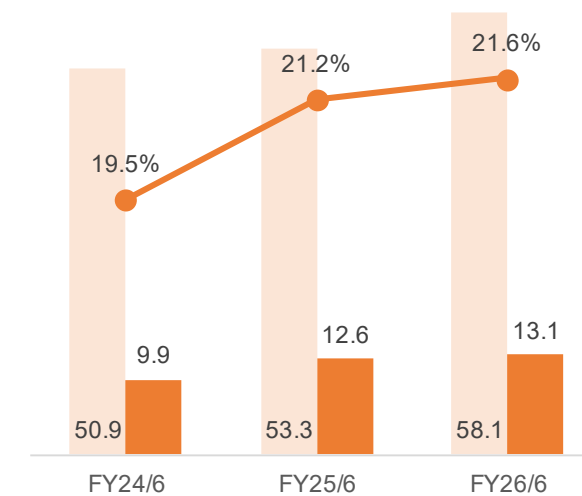
Operating Profit Margin

Net Sales Operating Profit Operating Profit Margin



SG&A Expenses

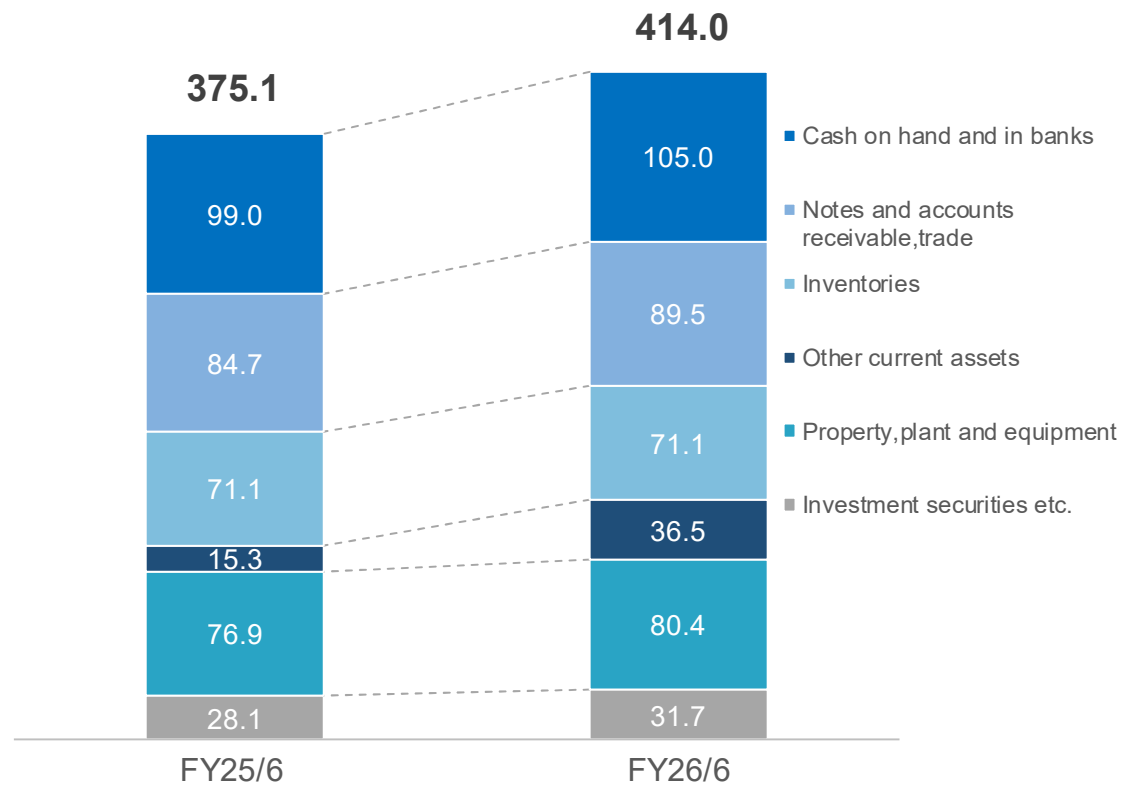
SG&A Expenses
R&D Expenses included in SG&A Expenses
SG&A Expenses to Net Sales ratio



Balance Sheet

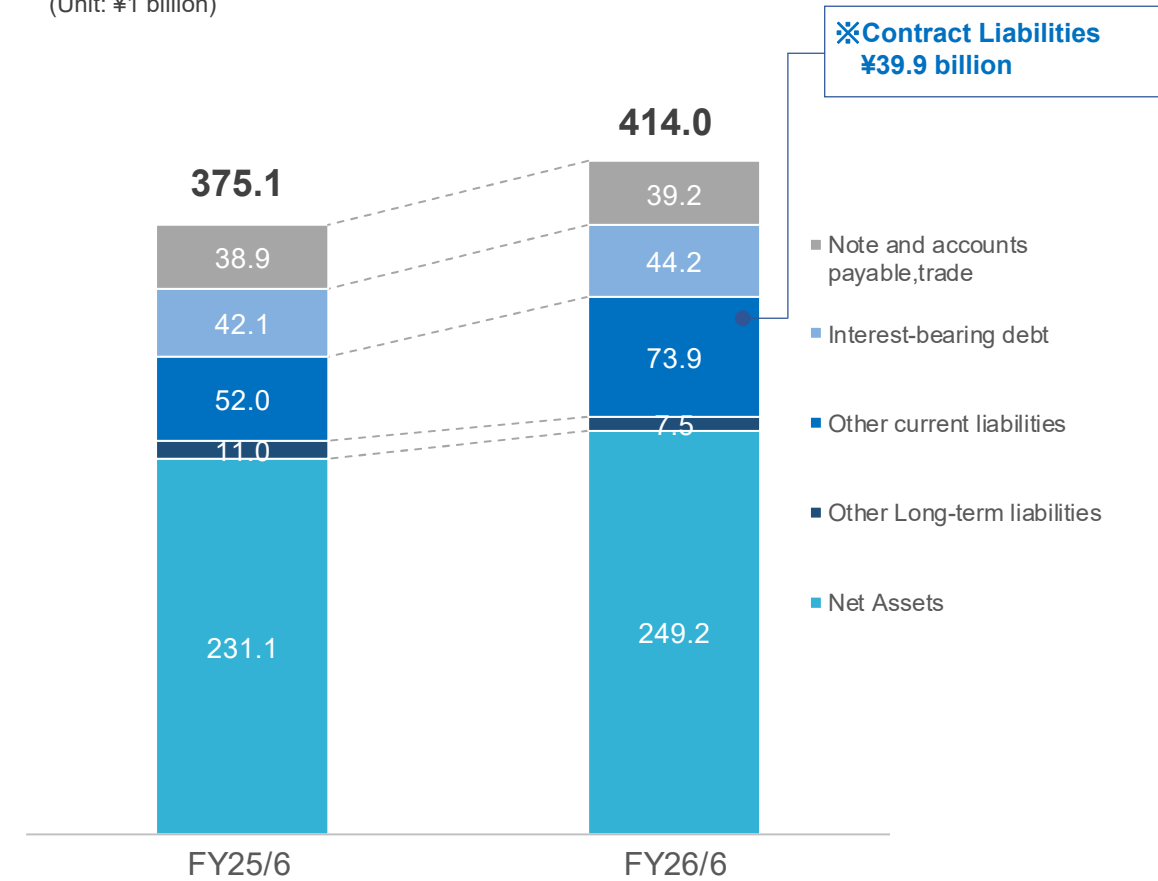
Assets

(Unit: ¥1 billion)



Liabilities and Net Assets

(Unit: ¥1 billion)



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FY2027/6 Financial Forecast

Financial Forecast

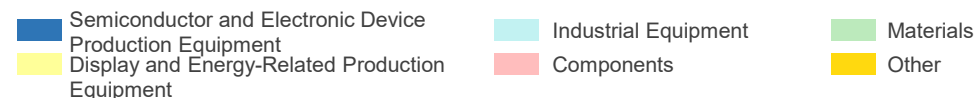
- Orders received and Net sales: The semiconductor business continues at a high level, despite factoring in a drop-off due to business reforms and a reactionary decline in Display-related business.
- Each profit item: Due to the contribution of highly profitable projects, the Gross profit margin is projected at 33.7% (+4.9 pt YoY), with plans for a significant improvement in the Operating profit margin as well.
- Shareholder returns: Unchanged from the previous fiscal year at ¥152 from the perspective of providing stable returns.

(Unit: ¥1 billion)	FY26/6	FY27/6 PLAN				YoY
		H1	H2	Full Year		
Orders Received	324.2	130.0	130.0	260.0	-64.2	-20%
Net Sales	269.1	125.0	130.0	255.0	-14.2	-5%
Gross Profit	77.7	41.5	44.5	86.0	+8.3	+11%
Gross Profit Margin	28.9%	33.2%	34.2%	33.7%	+4.9pt	-
Operating Profit	19.6	12.5	15.5	28.0	+8.4	+43%
Operating Profit Margin	7.3%	10.0%	11.9%	11.0%	+3.7pt	-
Profit attributable to owners of parent	17.1	8.0	11.0	19.0	+1.9	+11%
To net sales ratio	6.4%	6.4%	8.5%	7.5%	+1.1pt	-
Dividend per share(Yen)	152.0			152.0	±0	

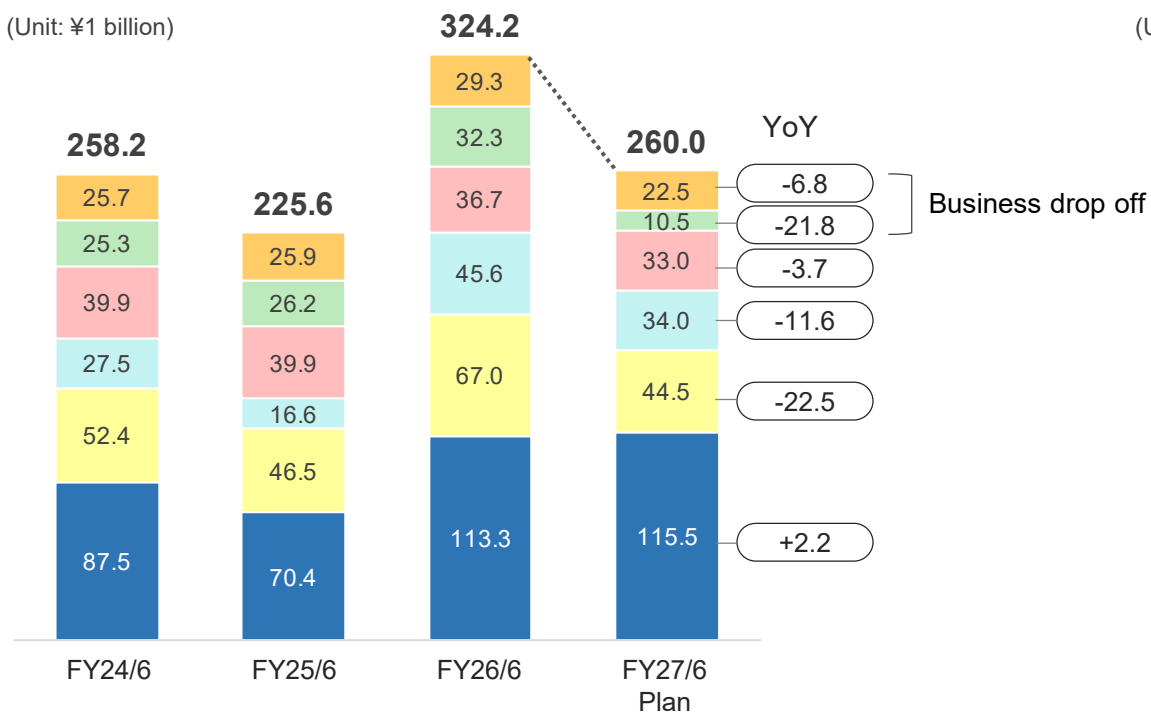
Orders Received and Net Sales Plan

- Orders received: Overall orders decreased due to a drop-off from business reforms and a reactionary decline in display-related business, but the semiconductor and electronics business continues at a high level.
- Net sales: While a drop-off from business reforms and a sales shift to FY2028/6 due to prolonged equipment L/T are occurring, the sales composition ratio of highly profitable projects is steadily improving.

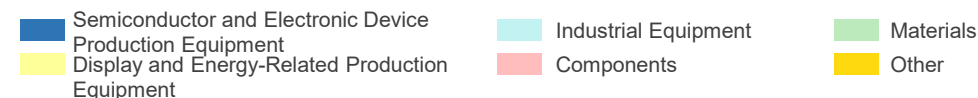
Orders Received



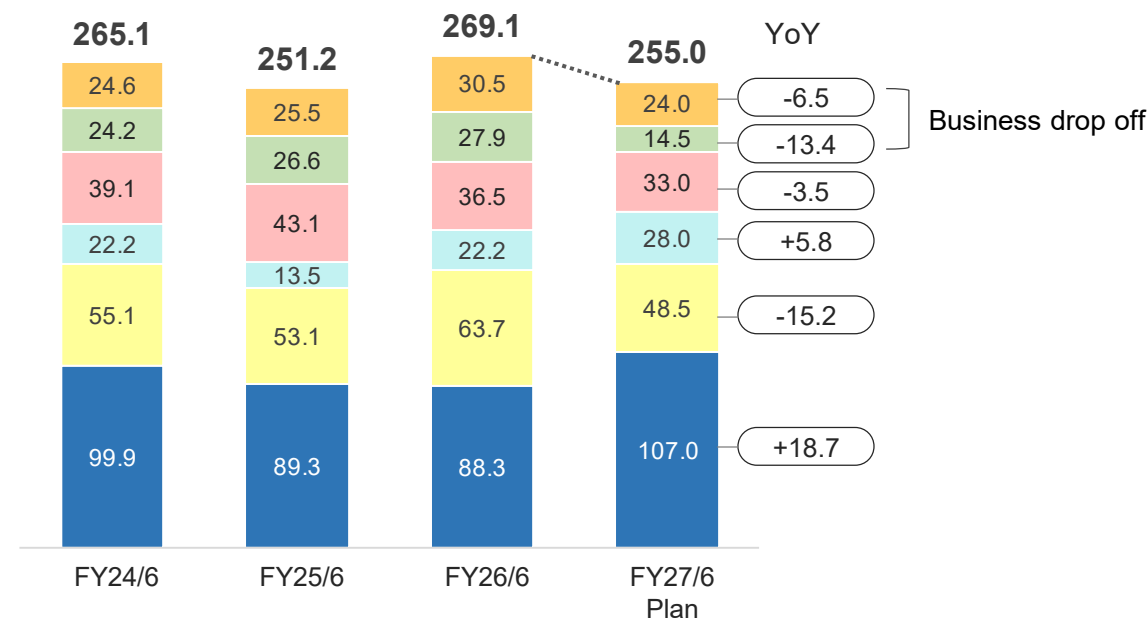
(Unit: ¥1 billion)



Net Sales



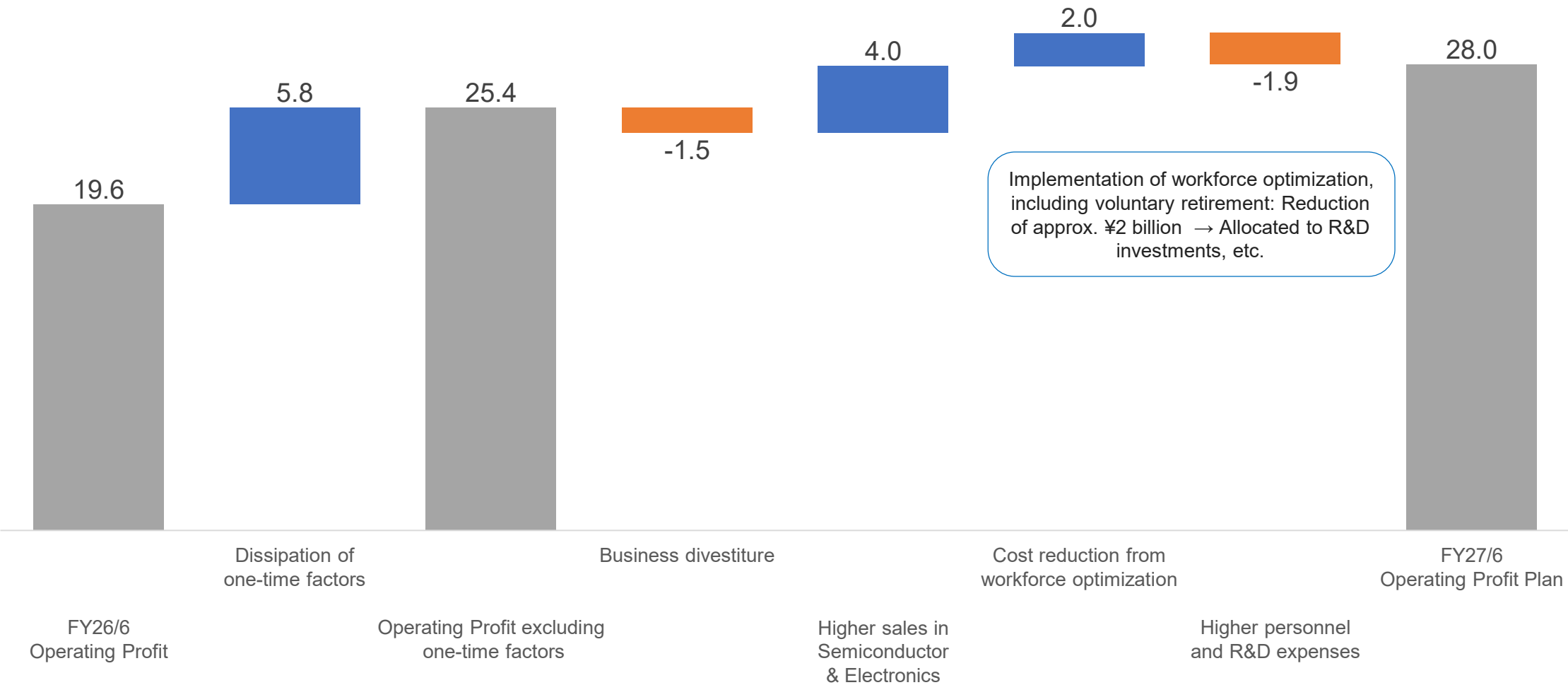
(Unit: ¥1 billion)



※ From FY26/6, orders received and net sales for leak testing equipment have been reclassified from the Components to the General Industry Equipment.

Operating Profit WF

- Laying the groundwork for solid growth: The partial drop-off in operating profit due to business divestitures is offset by 1)The fading impact of one-time factors, 2)Profit contributions from highly profitable Semiconductor · Electronics and Rare earth-related businesses, and 3)the effects of business reforms.



Profit Margin Plan

- Gross profit margin: Significantly improved to **33.7%** (+4.9 pt YoY), driven by Semiconductor and Rare earth-related businesses. **Steadily taking steps toward realizing the Value-up Plan.**
- Operating profit margin: 11.0% (+3.7 pt YoY) due to the improvement in the Gross profit margin and continued R&D investments.

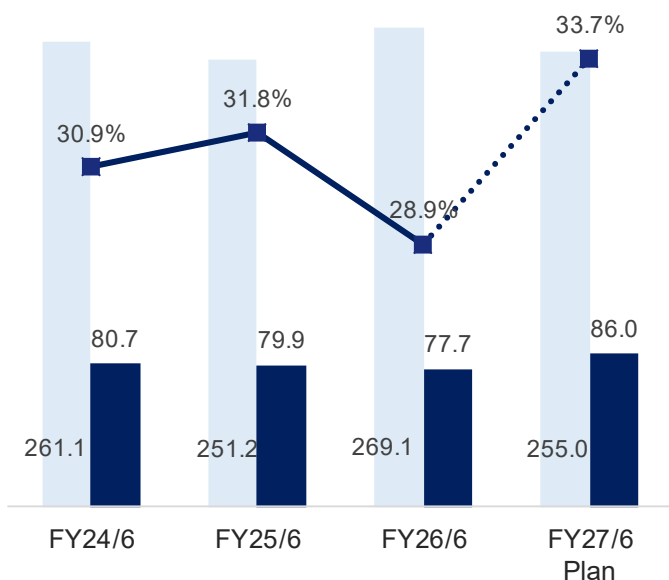
(Unit: ¥1 billion, %)

Gross Profit Margin

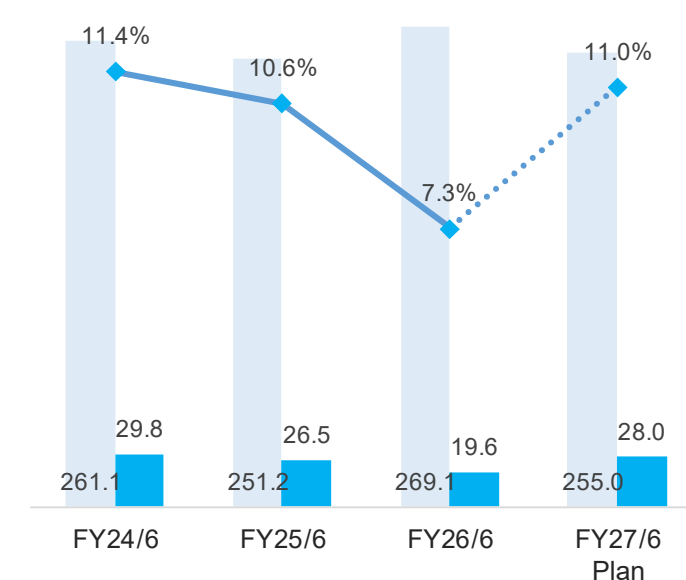
Operating Profit Margin

SG&A Expenses

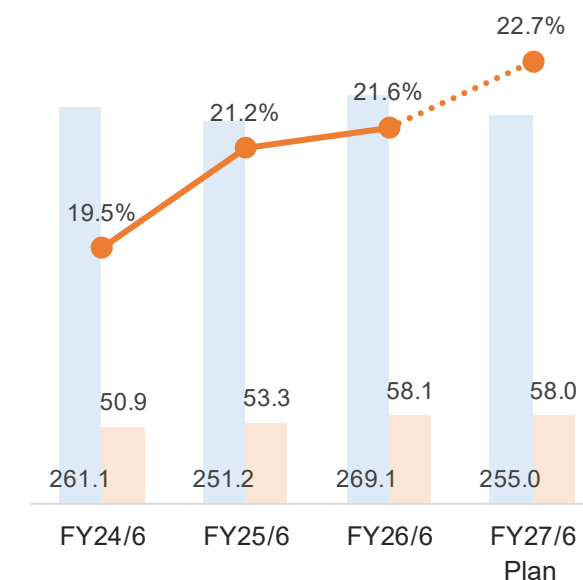
Net Sales Gross Profit Gross Profit Margin



Net Sales Operating Profit Operating Profit Margin



Net Sales
R&D Expenses included in SG&A Expenses
SG&A Expenses to Net Sales ratio



3

Progress of the Value-up Plan

Changes in the external environment since formulation of Value-up Plan (Aug. 2025)

While Physical AI market growth is expected, AI • Data center-related businesses are currently expanding rapidly.



To realize the Value-up Plan

Leveraging proven execution capabilities and a solid track record in AI • Data center-related businesses to capture the market in all directions and achieve strategic growth

First-Year Achievements

Growth Strategy

- Orders received achieved a record high of ¥324.2 billion
- Semiconductors business significantly outperformed the market

Business Reform

- Restructuring of display-related and low-margin businesses
- Reorganization of production bases

Production Reform

- Promotion of modular design
- 20% reduction in design man-hours / ¥1 billion reduction in variable costs



Challenges

Financial Performance

- Growth in Net sales and Operating profit is limited relative to the growth in Orders received

Production

- Material supply risks emerged
 - Supply chain constraints surfaced
- Shortening of manufacturing L/T (lead times) is only halfway complete
 - Constraints on production capacity

The inability to reliably convert Orders into Sales and Profit is a clear challenge for improving profitability

From "Comprehensive review and transformation" in FY2027/6 to "Realizing growth" in FY2028/6 and onward

- A crucial year to establish a foundation for rapid growth in FY2028/6 and onward, by comprehensively reviewing past initiatives in response to changes in the business environment and decisively executing necessary transformations

Growth Strategy

Strategic Theme

AI · Data Center-related Business

- Identify core strengths and concentrate management resources into priority areas.
- Achieve high growth and high profitability by increasing the composition ratio of advanced, high value-added projects.

Business Reform

Policy to advance a fundamental review of the business portfolio to optimize management resources and flexibly consider additional measures.

● Complete Current Plans

- FY2026/6: Deconsolidation of 4 companies. FY2027/6: Execution of deconsolidation for the remaining 4 companies.
- FY2026/6: Completion of Tohoku plant restructuring. FY2027/6: Implementation of Korea plant restructuring.

● Additional Measures

- Policy to additionally consider the sale or downsizing of businesses with low strategic fit.

● Fixed Cost Reduction

- Implementation of workforce optimization, including voluntary retirement: Reduction of approx. ¥2 billion → Allocated to R&D investments.
- redefine head office functions, the fixed cost structure, and business portfolio reforms

Production Reform

Challenge: Unable to convert orders into sales and profit growth due to material supply and production constraints.

Fundamentally review the entire production system

Strengthen
Procurement

+

Improve efficiency
Logistics

+

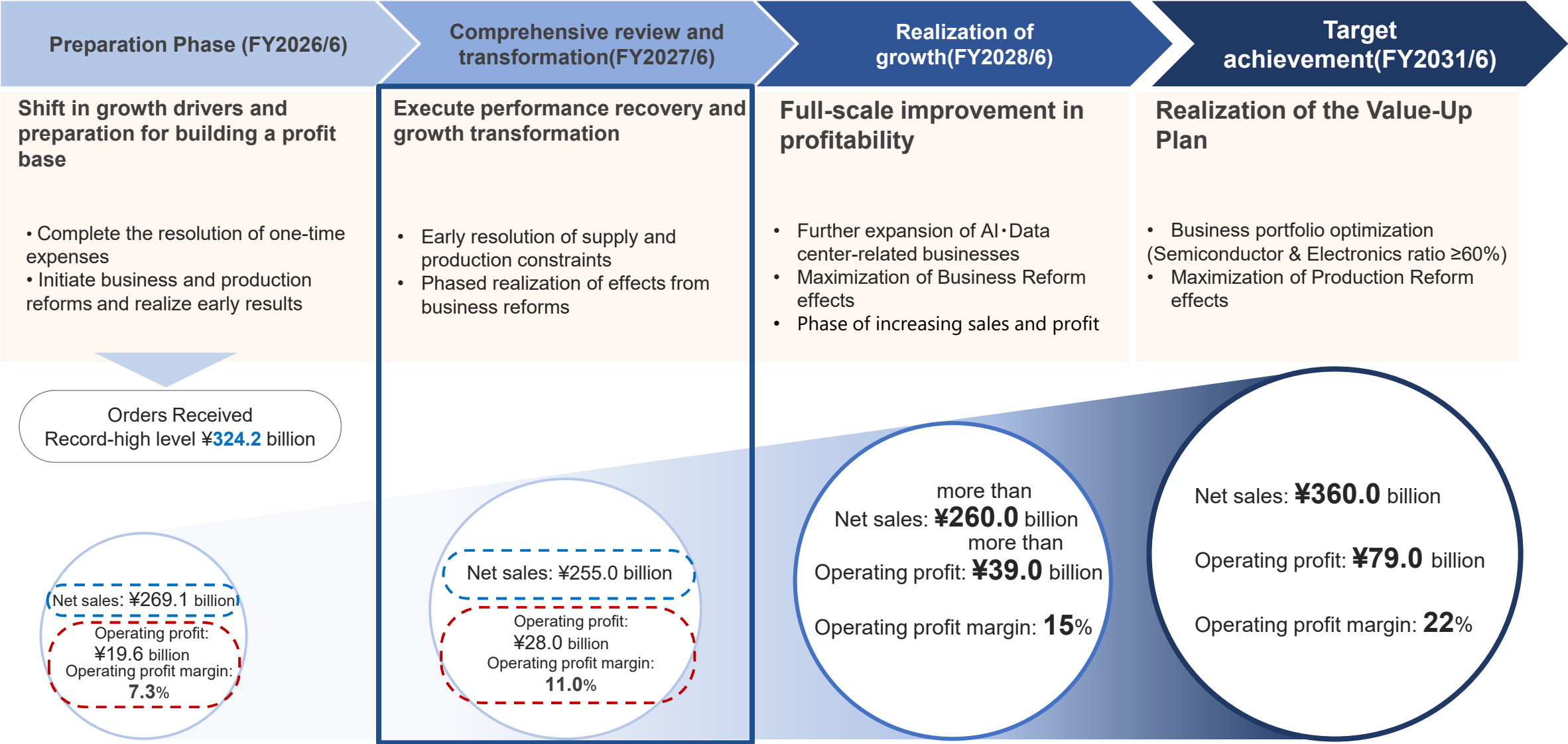
Increase
Production

Optimize production and logistics bases in conjunction with business reforms, aiming to shorten equipment L/T and increase capacity.

Reliably convert orders into sales and profit growth

▶ Lead to growth in FY2028/6 and onward.

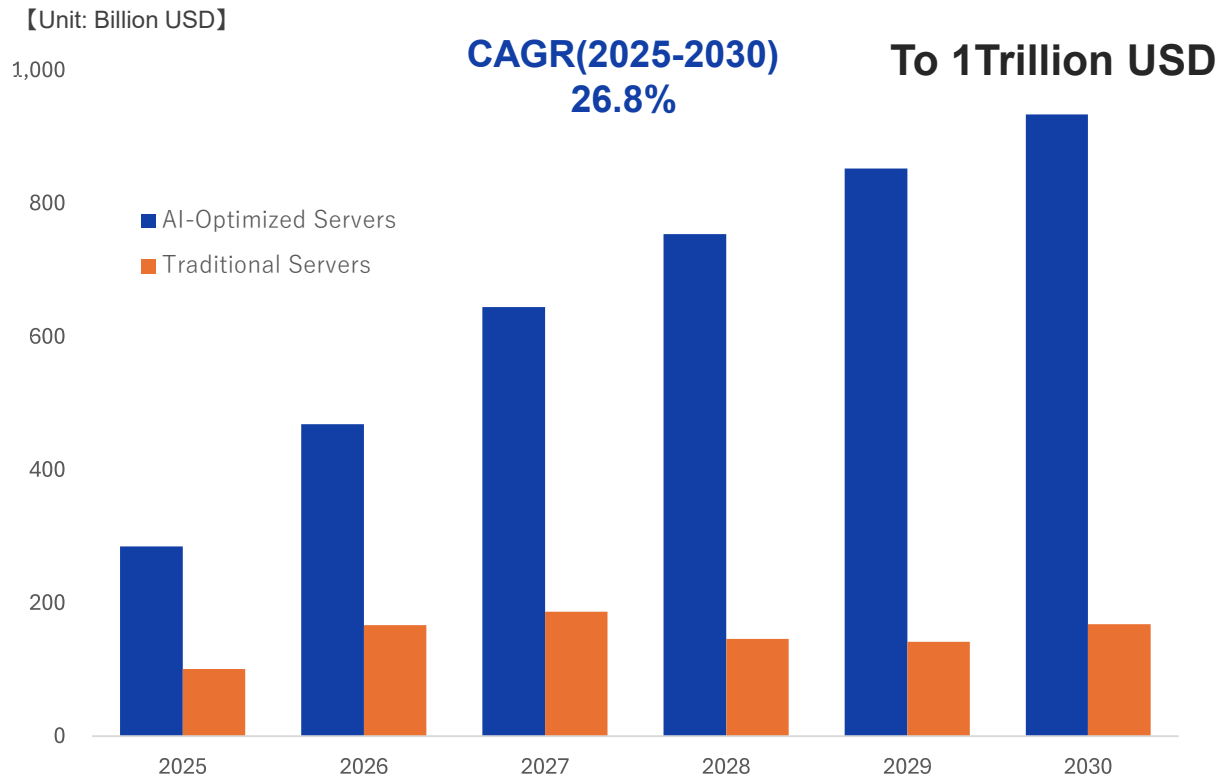
Toward reliable "execution" under new management for full-scale growth in the next fiscal year (FY2028/6)



Growth Strategy: Define the AI · Data center market as a strategic theme

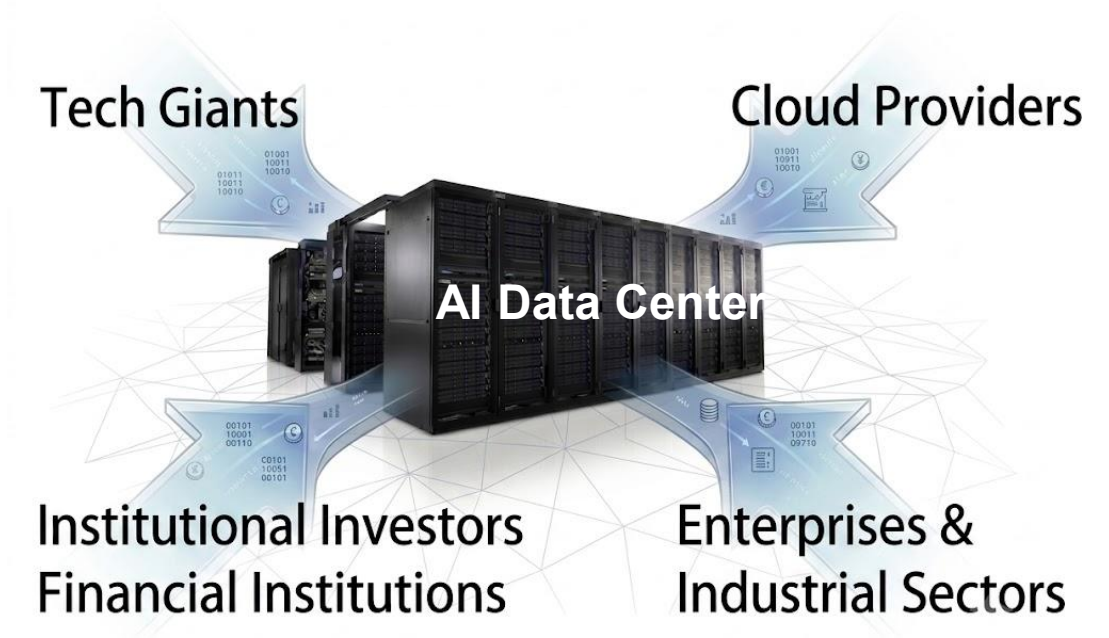
- Position the rapid expansion of the AI · Data center market as a growth opportunity and focus on advancing business development.

AI Data Server Investment Trends



Source: Gartner

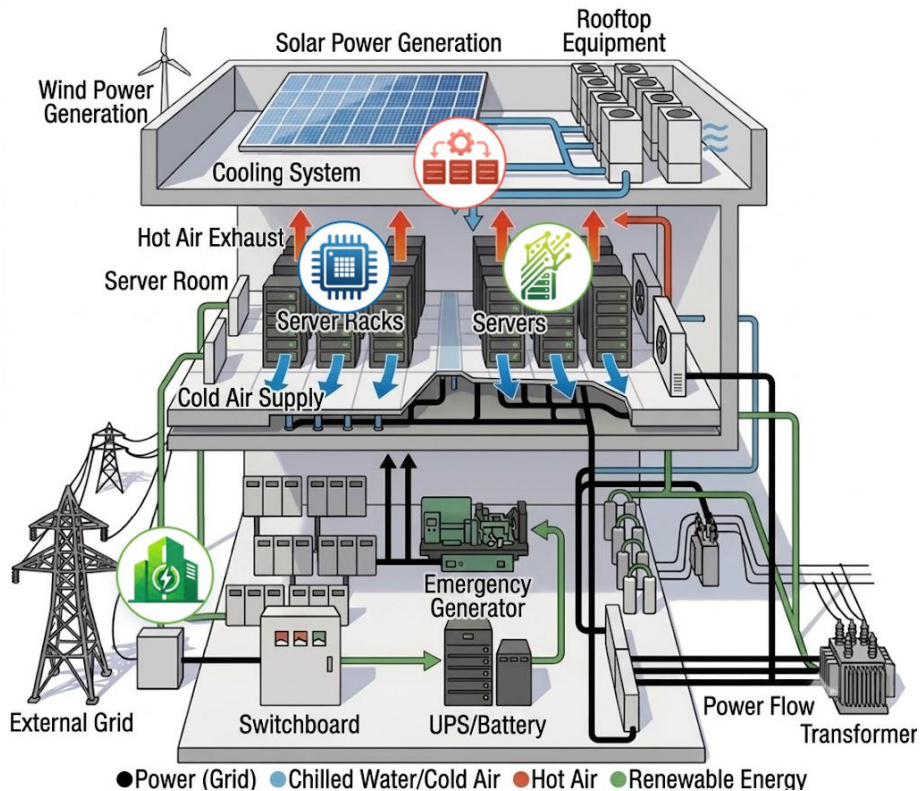
Global investment is concentrated in AI · Data centers



Growth Strategy: Capturing Key AI · Data Center Areas in All Directions

- Possessing a rich business track record and solid execution capabilities in the key areas of AI · Data centers, we will maximize these overwhelming strengths to capture the market in all directions and achieve strategic, robust growth.

Image of Data Center Interior



Major areas constituting AI · Data centers



Semiconductor Manufacturing

GPU/CPU
Storage

- Logic
- DRAM / NAND
- Advanced packaging, Materials
- HDD motors (Rare earth magnets)
- Device analysis and inspection



Data Communication

- Communication devices (optical devices, etc.)



Power Supply and Distribution Systems

- Power devices
- Film capacitors
- Power generation, transmission & storage systems
- Superconducting cables



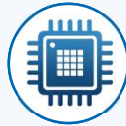
Infrastructure Equipment

- Forced liquid cooling panels
- Various pumps
- Chiller motors (Rare earth magnets)

Growth Strategy: Core Growth Engines

- In addition to Semiconductors (logic/memory) and Advanced packaging, Rare earth magnet-related business will also become a growth engine, strongly driving the growth of AI • Data center businesses.

Semiconductor Manufacturing

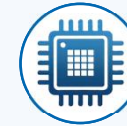


Logic / Memory

Providing solutions alongside the expanded application of hard mask films and metal process films

- Leveraging the superiority of our core "PVD" technology, we aim to expand our market share comprehensively, from new technology development in advanced nodes to horizontal deployment in mature nodes.

Semiconductor Manufacturing



Advanced Packaging

Solutions for WLP and PLP

- Deploying large-substrate ashing and sputtering technologies cultivated in the FPD business to PLP.
- Steadily capturing next-generation needs such as hybrid bonding with our proprietary fine plasma technology.

Infrastructure Equipment



Rare Earth Magnets

Business expansion through growing demand and supply chain diversification

- Acceleration of supply chain restructuring (reshoring of production) centered in the U.S.
- Proactive order acquisition using our vacuum melting furnaces and continuous sintering furnaces, which boast an overwhelming market share.

Growth Strategy: Omnidirectional acquisition through high-market-share products × comprehensive lineup

- Possessing a rare and extensive product lineup, including top-market-share products, to deliver “end-to-end” value to customers in the quality-driven AI • Data center market.

Top-market-share

Semiconductor Manufacturing



Surface Analysis and Inspection

Providing analysis and inspection solutions from R&D to semiconductor mass production lines

- Analytical instrument market: Dominant share of **over 50%**
- Commercializing semiconductor inspection equipment by applying surface analysis technology (To be released during FY2027/6)

Data Communication



Communication Devices

Expansion into optical devices and optoelectronic integration technologies that support high-speed, large-capacity data communication

- Reliably capturing the growth market by expanding sales of compound film deposition and processing equipment with a competitive edge, leveraging a **strong business foundation with top-share customers**

Infrastructure Equipment

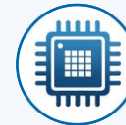


Leak Testing

Leak inspection applications for liquid cooling panels that solve thermal issues in AI servers

- Establishing a high-profit business with high-performance leak testing equipment holding a **high market share** in liquid cooling infrastructure where high reliability is required

Semiconductor Manufacturing



Materials

Technological response to the miniaturization and multi-layering of advanced semiconductors

- Contributing to customer yield improvement through collaboration with the semiconductor manufacturing equipment business
- Expanding business into semiconductor applications for tungsten, etc., utilizing **our strong powder metallurgy technology**

Power Supply • Distribution Systems



Power Devices

Reliably capturing the needs for power saving and high efficiency in data centers

- Omnidirectional deployment with **high-share IGBT: Backside electrode formation sputtering, and SiC: Ion implantation equipment**
- Deployment of **GaN sputtering** from Europe

Infrastructure Equipment



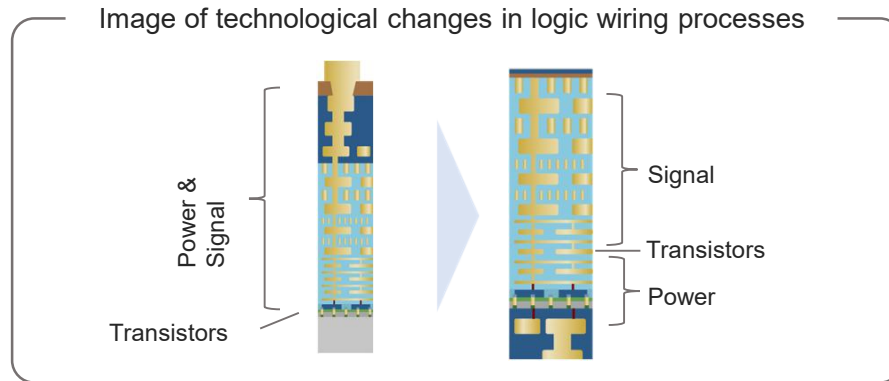
Components

Creating strong synergies with our equipment

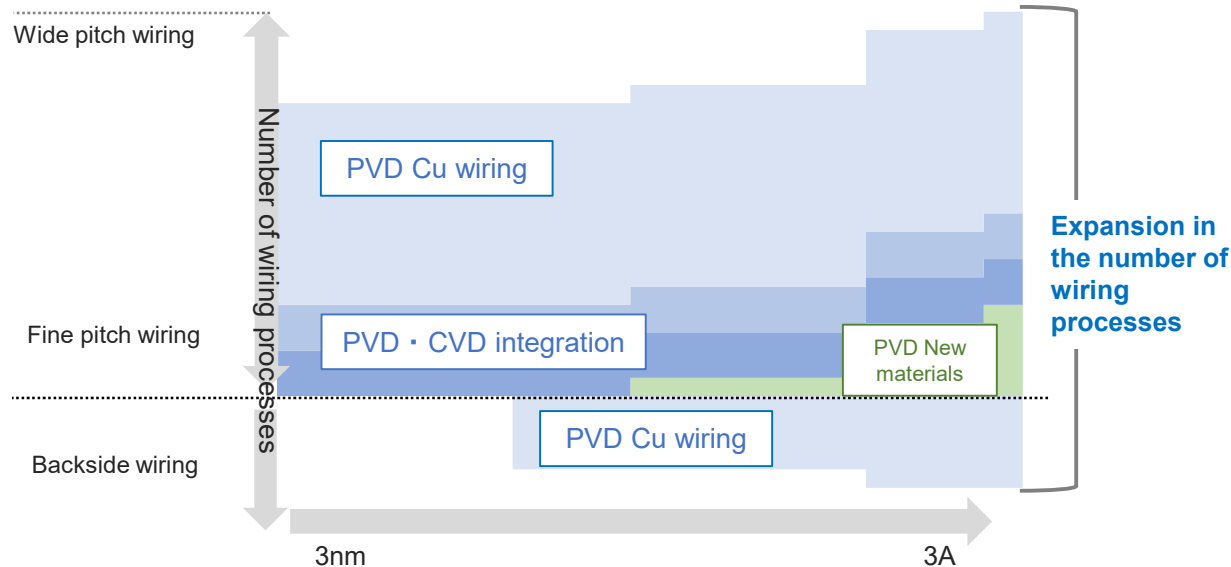
- Deployment of **highly reliable pumps, measuring instruments, and power supplies** that support the performance of AI • Data center-related equipment (semiconductors, leak testing, etc.)
- Expanding applications to next-generation fields such as quantum computers by leveraging **cryogenic technology**

Growth Strategy: Semiconductors (Logic / Memory)

- With increasing transistor density, the application of hard mask films is expanding, and the number of wiring processes is increasing.
- The importance of the core technology "PVD," which is essential for both processes, is growing. Aim for sustainable high profitability by leveraging technological superiority.



Logic wiring process roadmap



Expanding the application range of hard mask films



Stress control film formation technology

FY27/6~

- Accelerate horizontal rollout to mature node MHM (metal hard mask) processes.

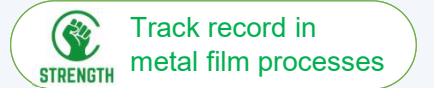
FY28/6~

- Expand application of amorphous silicon HM.

FY29/6~

- Adoption of PVD in wafer backside power delivery and bonded structures.

Approach to wiring processes



Track record in metal film processes

—Memory—

FY27/6~

- Expansion of wiring processes (BEOL+RDL).

—Logic—

FY28/6~

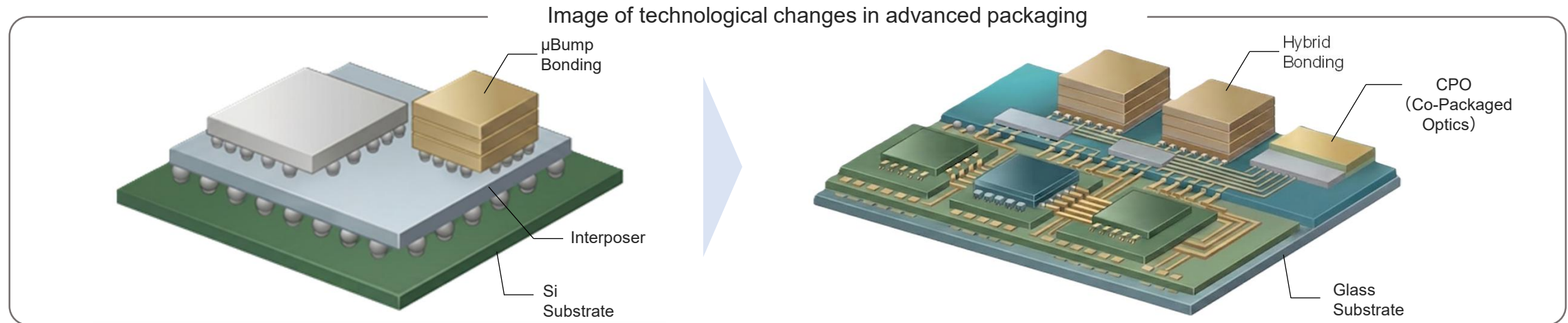
- Acquire POR for Cu wiring processes (Wide pitch, Backside power)

FY29/6~

- Mass production application of PVD/CVD integration technology.
- Advanced development of new materials (PVD).

Growth Strategy: Advanced Packaging

- Application processes for our equipment are expanding alongside the sophistication of "advanced packaging technology," which determines the performance of next-generation semiconductors.
- Integrate our elemental technologies in both the semiconductor and electronics fields to capture a solid share in the expanding market.

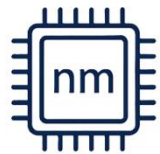


FY27/6~



Micro-plasma Technology

FY29/6~



Advancement of miniaturization accompanying system performance improvements

- Sophistication of interposer substrates: Expansion of ashing equipment for descum and desmear processes using plasma technology (de facto standard).



Panel Film Deposition Technology
(application of FPD technology)



Increasing substrate size accompanying the increase in mounted components

- Panelization and upscaling of interposers and substrates: Expansion of ashing and sputtering equipment.



Hybrid Bonding



CPO
(Co-Packaged Optics)



Glass Substrate

Maximizing wiring density through direct electrode bonding

→ Surface activation using plasma technology.

Realization of ultra-high-speed, low-power communication

→ Film deposition and processing of compounds (thin-film lithium niobate).

Prevention of distortion accompanying the upscaling and miniaturization of substrates

→ Ashing and sputtering technology cultivated in FPD.

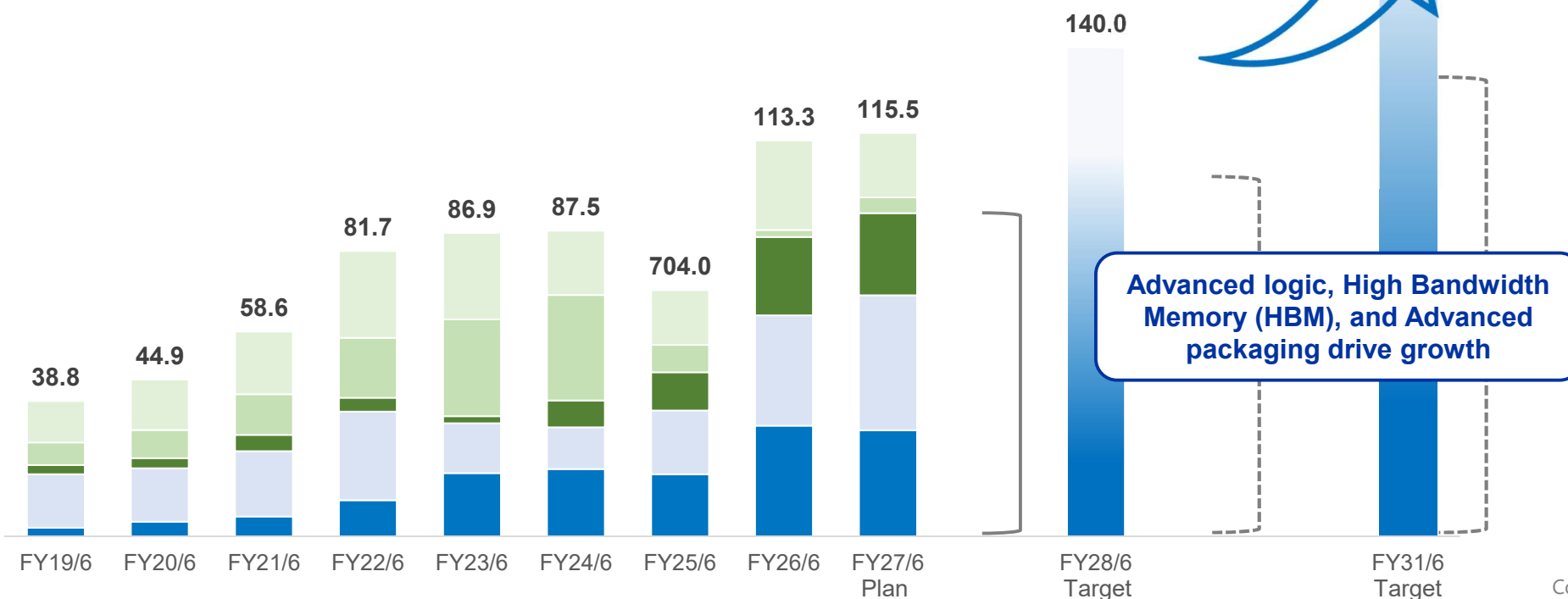
Semiconductor and Electronics: Growth Trajectory toward Orders received exceeding ¥200 billion

- In the semiconductor and electronics field, application processes for our equipment are expanding against the backdrop of market expansion related to AI and data centers.
- The rising composition ratio of advanced, high value-added projects drives improvements in profit margins alongside order growth.

Orders Received in Semiconductor and Electronics

■ Logic ■ Memory ■ Packaging ■ Power Device ■ Electronic Device

(Unit: ¥1 billion)



〈Core products〉



Sputtering Equipment



Ashing Equipment



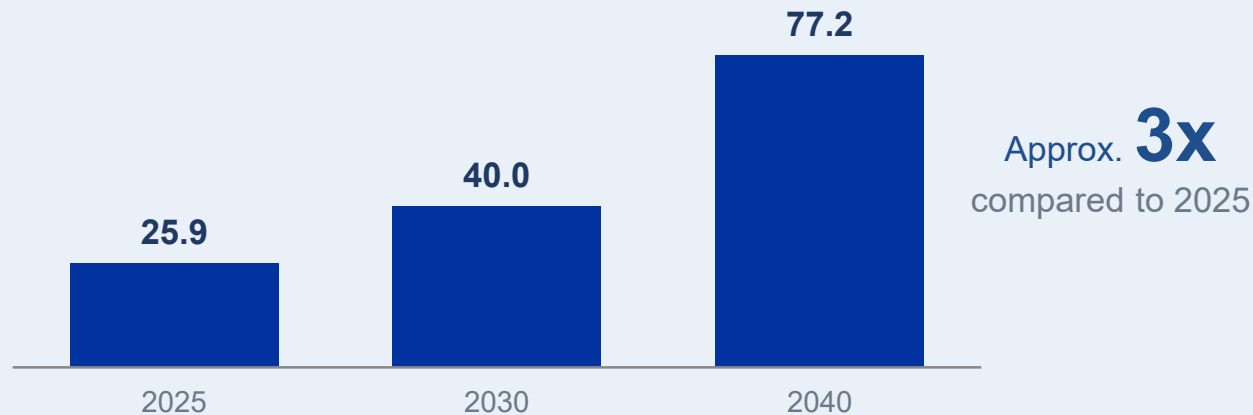
Etching Equipment

Growth Strategy: Rare Earth Magnet-Related Business

- Rapid growth of the essential rare earth magnet market, driven by explosively expanding AI • Data center demand. Reliably capturing the massive global demand for neodymium magnets—projected to surge to "approximately 3× current levels by 2040"—and driving robust business expansion.

Market Growth

Volume basis: Global demand (ktons/year)



Key Points of the U.S. Market

- U.S. demand accounts for approximately **18%** of the global total.
- As of 2025, supply **relies on imports**.
- Supply capacity will be strengthened toward 2030, and is expected to cover about **30%** of demand, but supply remains **insufficient**.

Demand — Four Structural Drivers



Rapid demand surge

AI • Data Centers



Primary application

EV traction motors



High growth

Physical AI



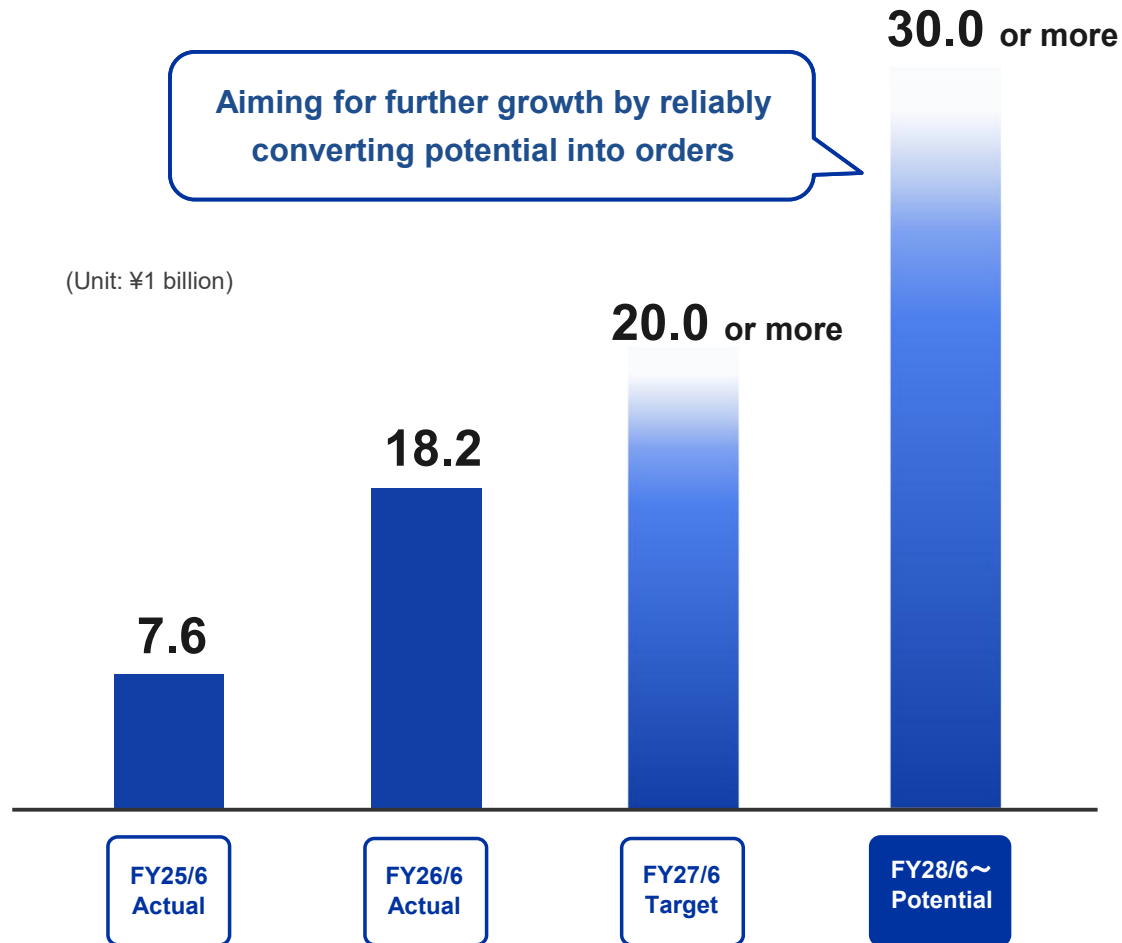
Renewable energy expansion

Wind power generation

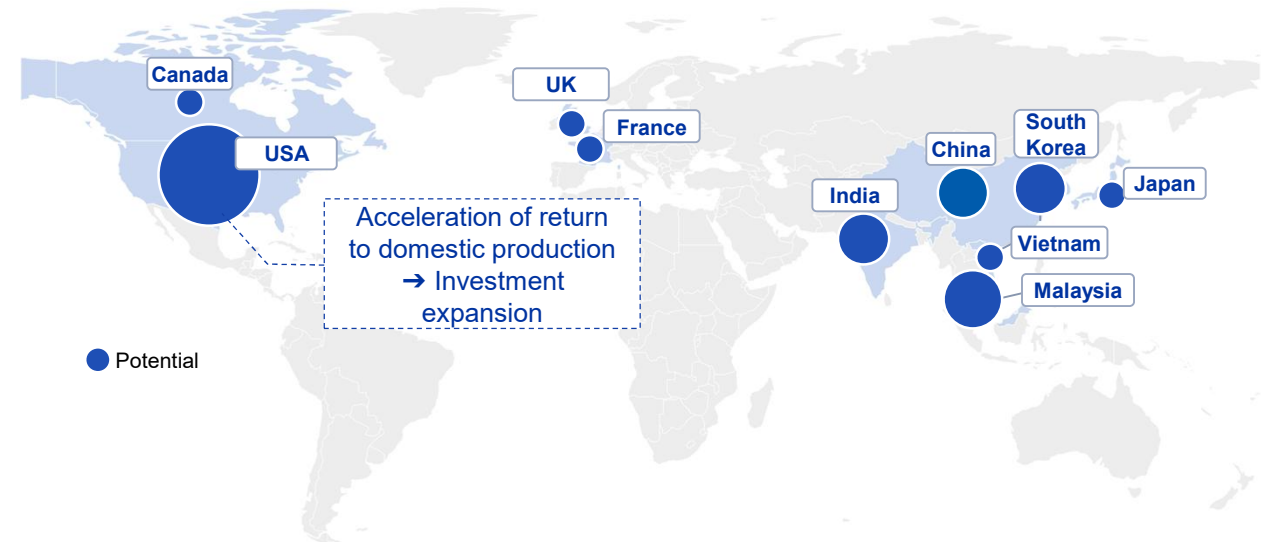
Trends in Orders Received for Vacuum Furnaces (Rare Earth Magnet-Related)

- Steady accumulation of high-margin projects and reliable realization of improved profitability, driven by the strong tailwind of expanding investments associated with supply chain diversification

Trends in Vacuum Furnace Orders Received



Diversification of the Supply Chain



〈Core products〉



Vacuum Melting Furnace



Batch-type Vacuum Furnace



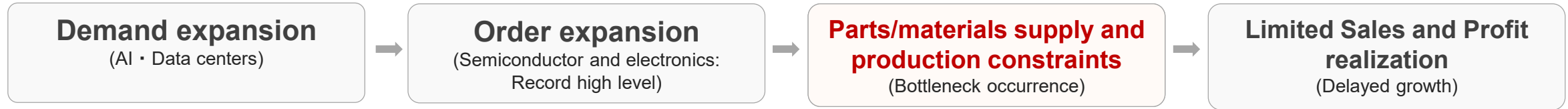
Continuous Vacuum Sintering Furnace

- While business divestitures and production sites restructuring have made steady progress, the impact on improving profitability has been limited. Under the new management structure, we will review head office functions, the fixed cost structure, and business portfolio reforms to accelerate business transformation.

Measures	Previous Term (FY2026/6)	Current Term (FY2027/6)
Business divestiture, downsizing, etc.	- Transfer of materials business (China) - Transfer of pump motor business - Closure of CS bases in Southeast Asia - Partial withdrawal from the parts processing business Deconsolidation of consolidated subsidiaries 4 Companies / out of 8 targeted	- Planned transfer of materials business (South Korea) - Other businesses: Planned transfer of 3 companies Deconsolidation of consolidated subsidiaries 8 Companies / out of 8 targeted - Review head office functions, fixed cost structure, and business portfolio
Production sites restructuring	- Withdrawal from materials-related production (Tomisato Plant, Japan) - Restructuring of Tohoku Plant → Workforce optimization including voluntary retirement: Reduction of approx. ¥2.0 billion Progress rate of workforce optimization Approx. 40%	- Review overall optimization, including the reorganization of production and logistics bases, with an eye toward net sales of ¥360.0 billion in FY2031/6 - Continue to reduce fixed costs through operational efficiency improvements, etc.

Overall optimization through Production reforms + Reorganization of production and logistics bases

- Fundamentally review the entire production system to achieve early resolution of parts/materials supply and production constraints and promote the maximization of sales and profits as the highest priority.
- Continue to promote efforts to expand the modular design ratio targeted in production reforms.



Concentrated measures for FY2027/6

	Measures	Effects	
Procurement	Review and execute supplier strategy	Shorten parts/materials procurement L/T	
Logistics	- Consolidate logistics warehouses at each factory→Improve efficiency by promoting automation - Convert logistics space into production space→Increase production capacity	- Increase capacity - Improve production efficiency - Reduce costs	
Production	- Semiconductor and electronics: Consider capacity expansion investment at Kyushu Plant - Rare earth-related: Start production at Chigasaki Plant	- Increase capacity - Improve production efficiency	

Complete structural development during FY2027/6 → Lead to sales and profit improvement in FY2028/6

Continue promoting production reforms (~FY31/6)

Reduce design man-hours and shorten L/T

- Realize customer specifications through compatible designs without changing drawings

Shorten procurement L/T and reduce variable costs

- Component standardization and planned bulk ordering
- Procurement of parts in line with the assembly schedule

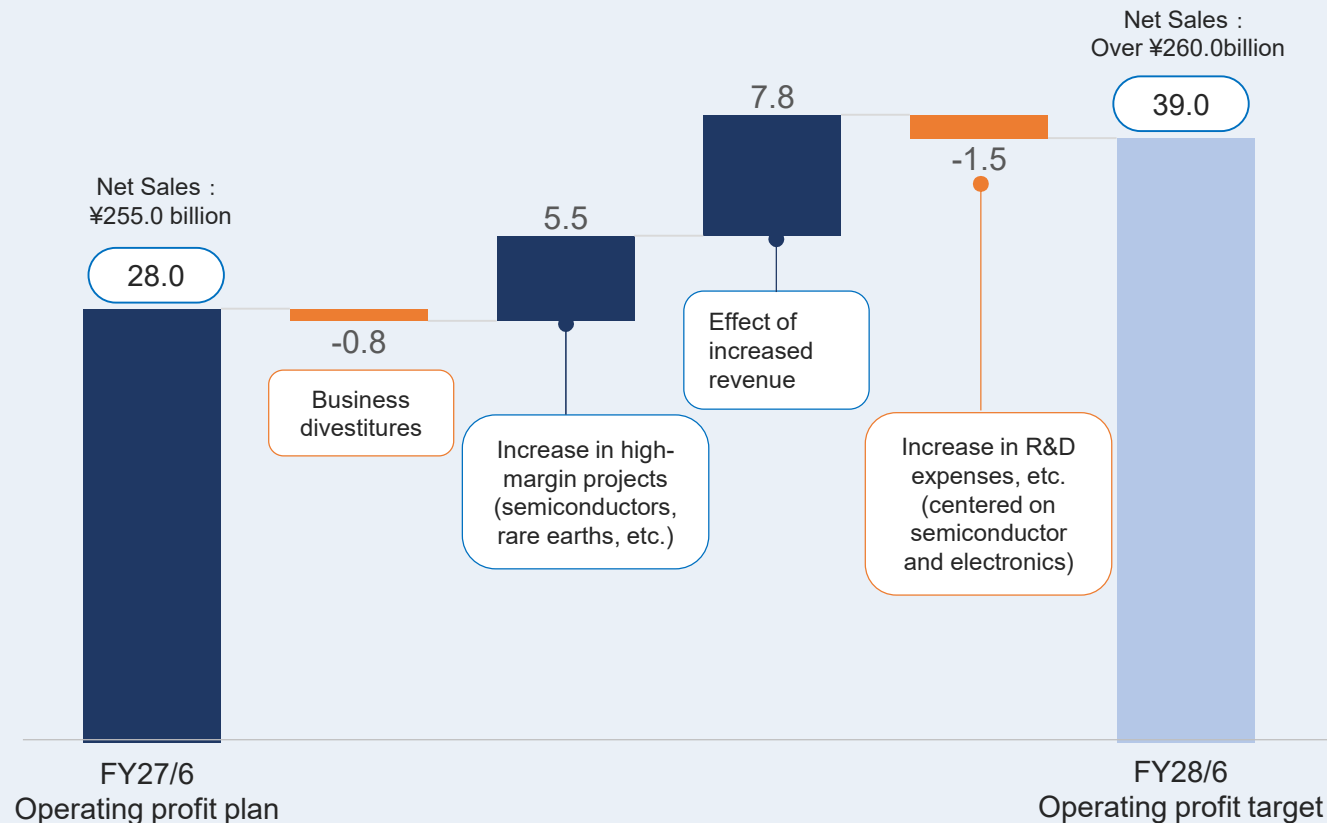
Shorten manufacturing L/T and reduce man-hours

- Optimization of production lines through standard assembly and planned production

Realization of reforms / Profitability expansion driven by increased business for AI · Data centers

Toward FY2028/6

Steadily link order expansion to increases in sales and profit



Toward FY2031/6

Realization of mid- to long-term management plan targets

FY31/6 Target Net Sales : ¥360.0billion
Operating profit : ¥79.0billion

Operating profit growth (compared to FY28/6)

- Revenue increase : **Approx.¥32.0 billion※**
 - Improvement in profit amount due to expansion of orders and sales
- Improvement in profit margin and mix : **Approx.14.0billion※**
 - Accumulation of high-margin projects centered on semiconductor and electronics
- Increase in R&D expenses, etc.: **Approx.-60billion**

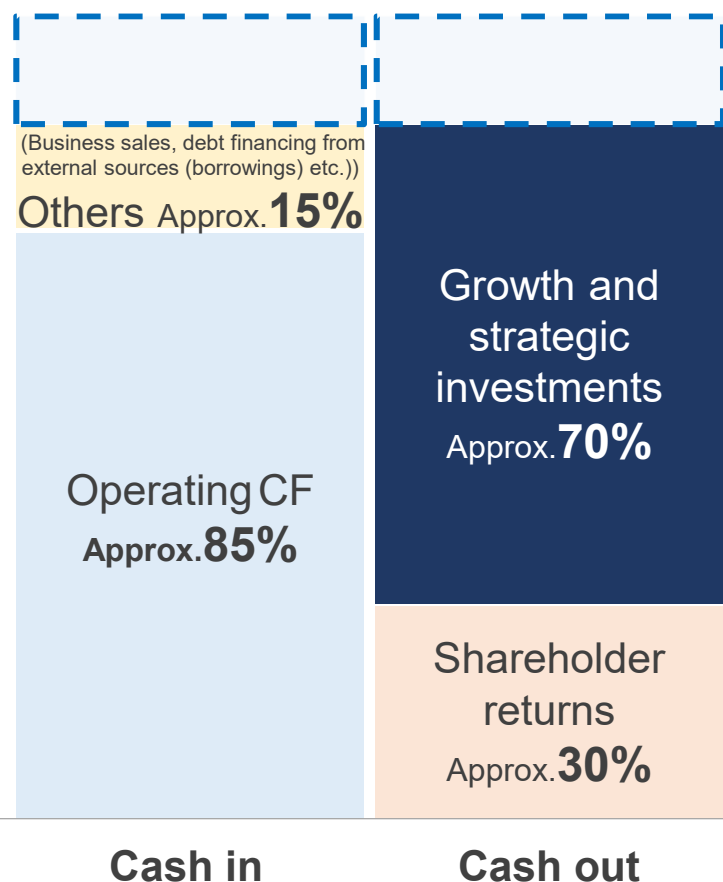
※Revenue increase and profit improvement:
For AI and data centers: Approx. 60-70%

- In order to maximize profit opportunities in the AI・Data center areas, we will execute growth investments that outpace market growth as well as production-related investments. Furthermore, keeping agile additional investments in scope, we will ensure this leads to solid profit growth.

Capital Allocation

(Cumulative total for 6 years: FY2026/6 - FY2031/6)

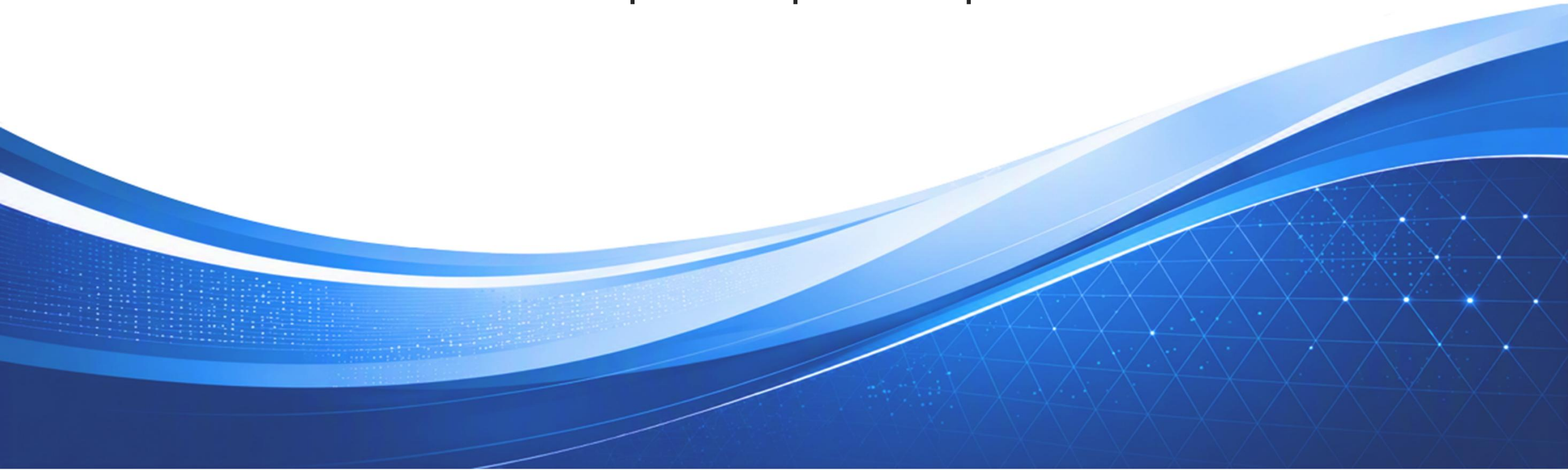
Considering flexible additional investments in response to growth opportunities



Investment areas	Main purposes	Contribution to plan
AI・Data center-related businesses (Semiconductor and electronics, rare earth-related, etc.)	R&D, evaluation/demo equipment, response to advanced processes Strengthen production capacity, respond to customer projects, respond to supply chain	Convert market growth into orders and profits Reliable acquisition of growth projects
Optimization of production and logistics bases	Base reorganization, inventory optimization, logistics efficiency improvement	Shorten L/T and reduce costs
M&A	Acquire complementary technologies, customer bases, and regions	Expand options for medium- to long-term growth

Aim to further expand shareholder returns

To securely capture the growth of the AI · Data center markets,
we will complete the “comprehensive review and transformation”
driven by the new management structure and fully transition to
the “profit expansion phase”



Appendix

Business results (Quarterly)

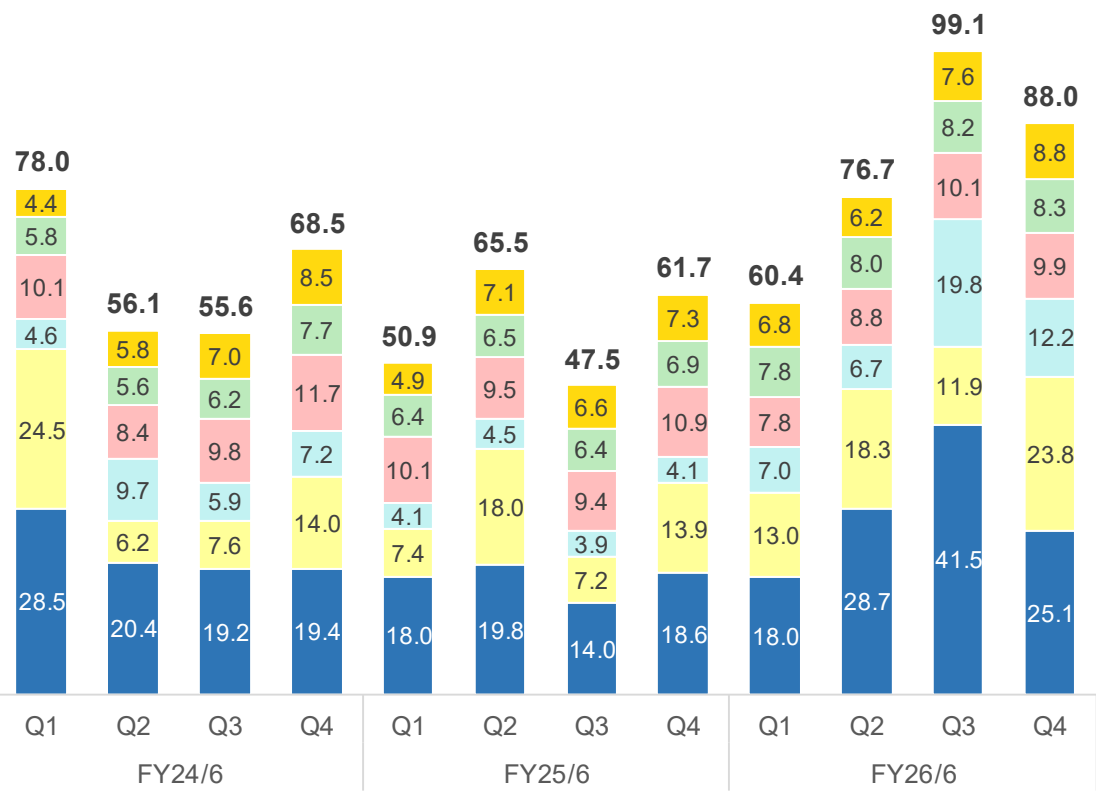
(Unit: ¥1 billion)	FY2025/6					FY2026/6						
	Q1	Q2	Q3	Q4	Full Year	Q1	Q2	Q3	Q4	Full Year	YoY	
Orders Received	50.9	65.5	47.5	61.7	225.6	60.4	76.7	99.1	88.0	324.2	+98.7	+44%
Net Sales	61.0	73.9	52.9	63.5	251.2	52.7	71.2	67.7	77.5	269.1	+17.9	+7%
Gross Profit	19.1	23.8	17.6	19.3	79.9	15.7	20.7	21.7	19.7	77.7	-2.1	-3%
Gross Profit Margin	31.3%	32.2%	33.3%	30.5%	31.8%	29.7%	29.1%	32.0%	25.4%	28.9%	-2.9pt	
SG&A	13.4	14.2	12.2	13.6	53.3	13.4	14.5	15.4	14.8	58.1	+4.8	+9%
Operating Profit	5.8	9.6	5.4	5.8	26.5	2.3	6.2	6.3	4.9	19.6	-6.9	-26%
Operating Profit Margin	9.4%	13.0%	10.2%	9.1%	10.6%	4.3%	8.7%	9.2%	6.3%	7.3%	-3.3pt	
Profit attributable to owners of parent	3.7	6.7	2.7	3.6	16.7	1.7	4.5	2.9	8.0	17.1	+0.4	+2%
To net sales ratio	6.1%	9.0%	5.1%	5.6%	6.6%	3.2%	6.4%	4.3%	10.3%	6.4%	-0.3pt	

Orders Received & Net Sales (Quarterly)

Orders Received



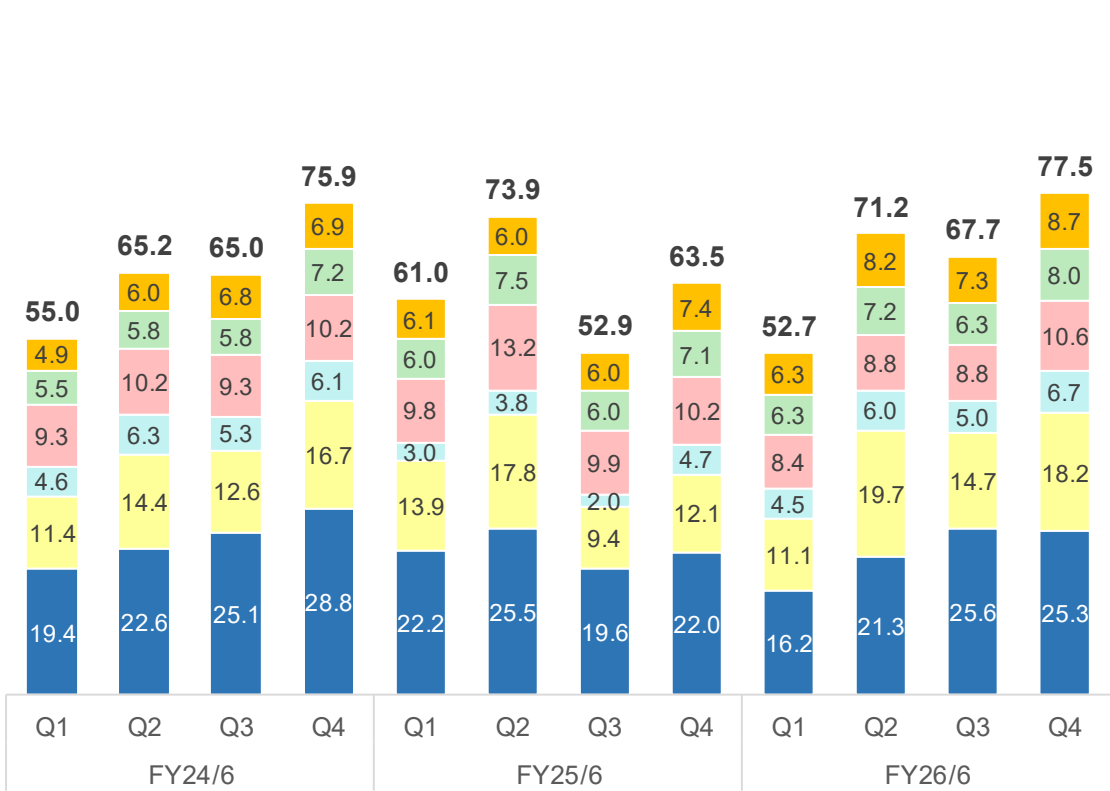
(Unit: ¥1 billion)



Net Sales



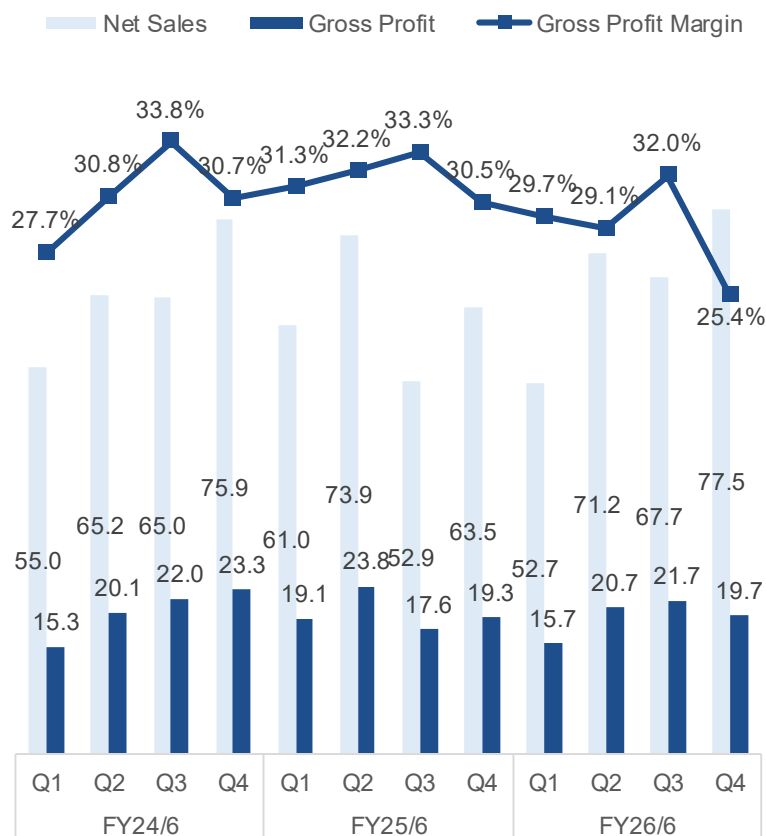
(Unit: ¥1 billion)



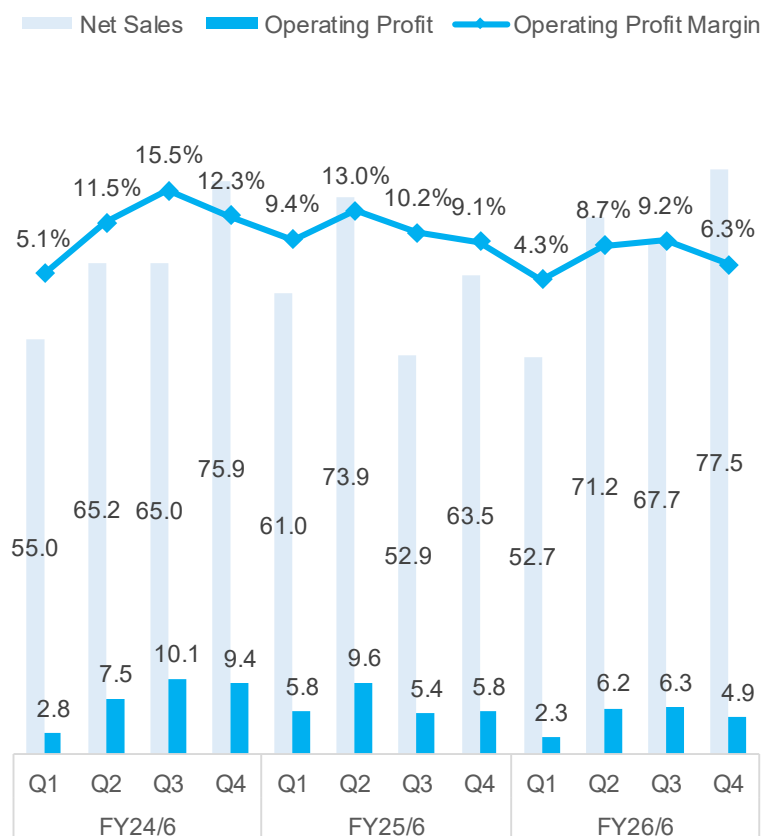
Profit Margin (Quarterly)

(Unit: ¥1 billion, %)

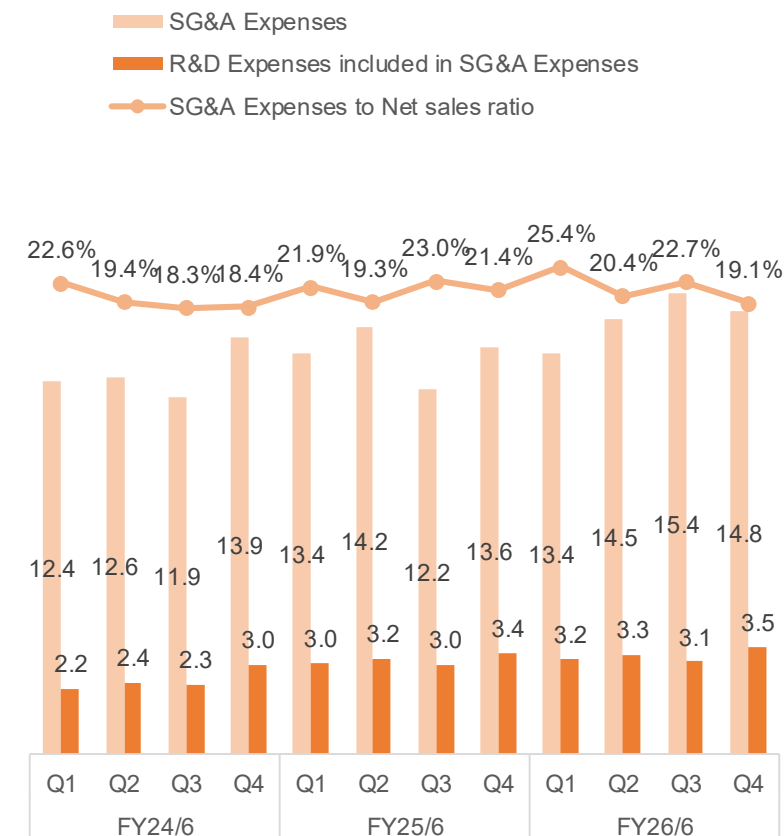
Gross Profit Margin



Operating Profit Margin



SG&A Expenses

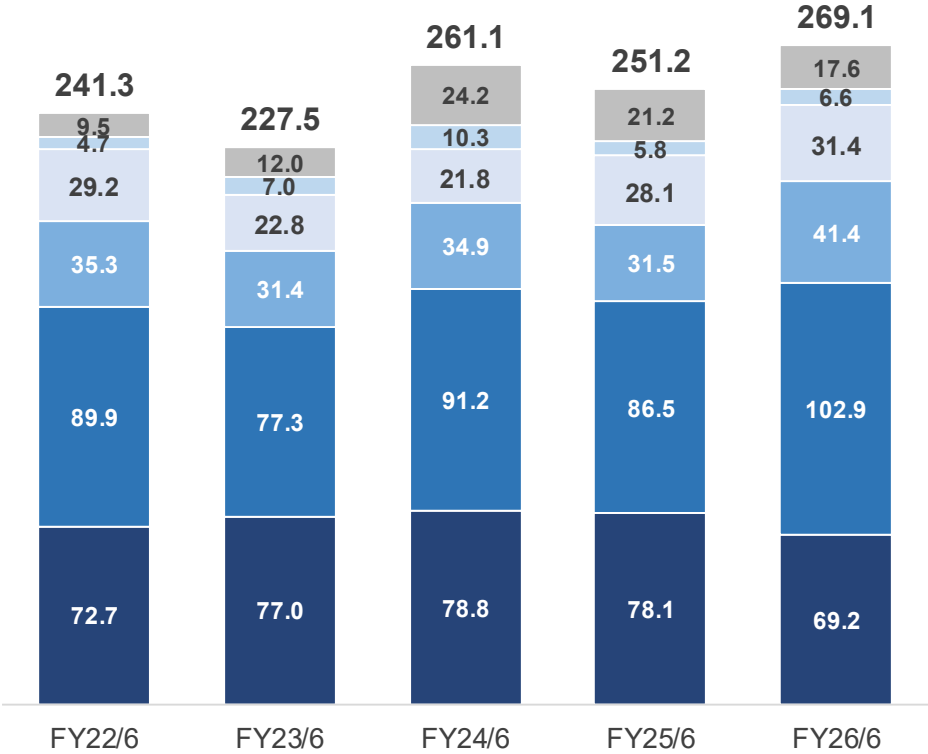


Net Sales by Region (Actual)

Net Sales

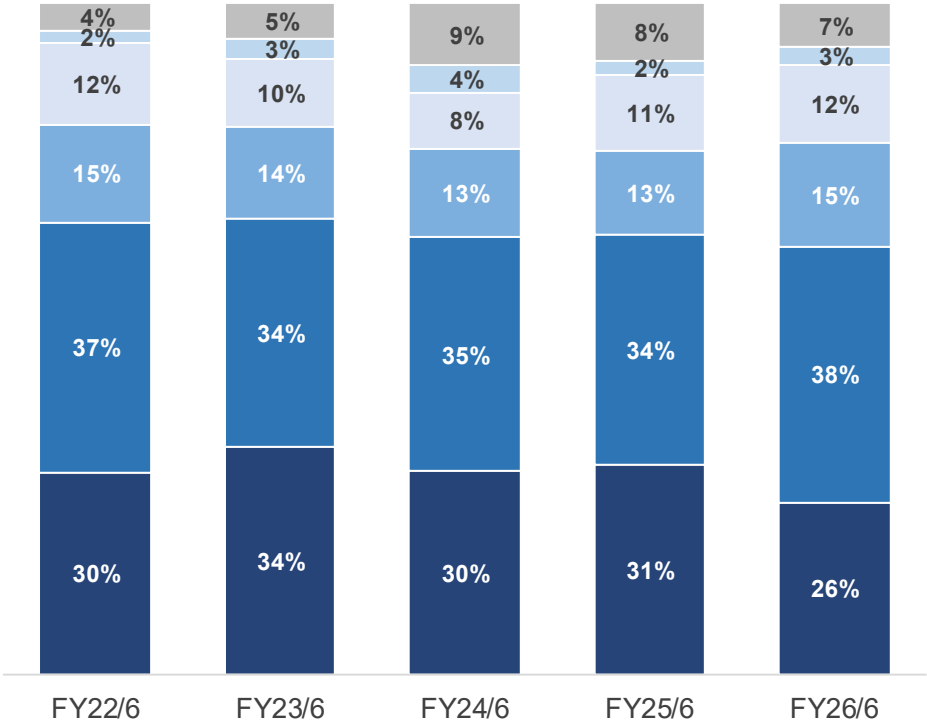
■ Japan ■ China ■ Korea ■ Taiwan ■ Other Asia ■ Europe,others

(Unit: ¥1 billion)



Net Sales Ratio

■ Japan ■ China ■ Korea ■ Taiwan ■ Other Asia ■ Europe,others

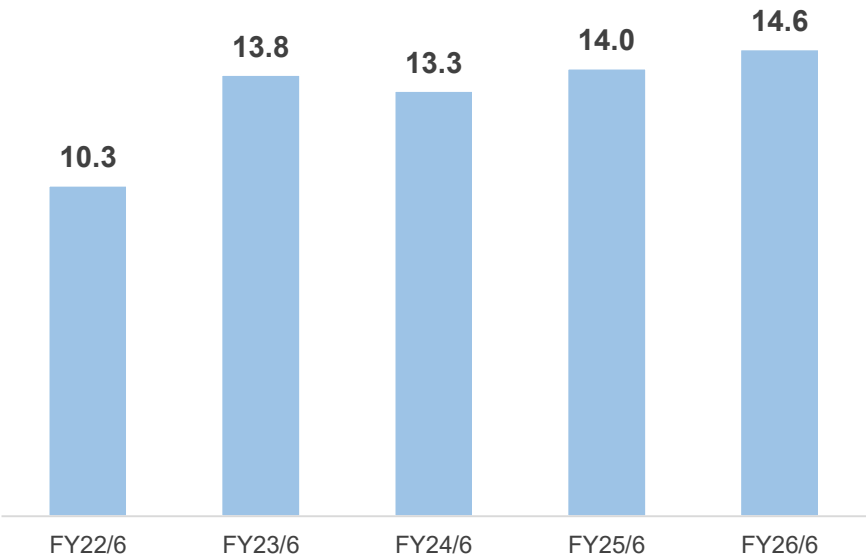
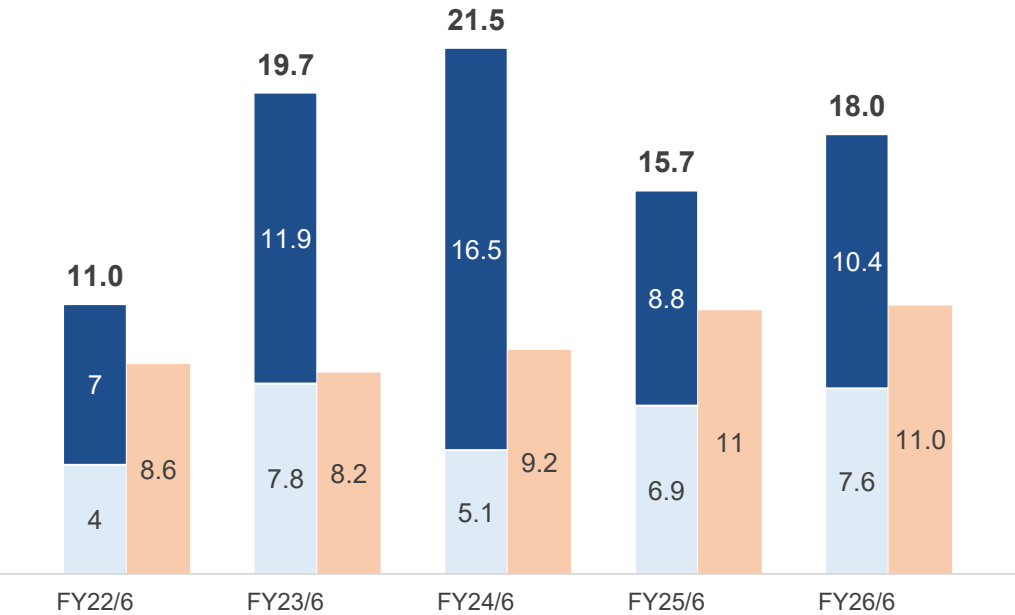


Capital Expenditures

R&D Expenses*

■ Building and production facilities.etc. (Unit: ¥1 billion)
■ R&D facilities ■ Depreciation

(Unit: ¥1 billion)



*R&D expenses included in manufacturing fixed costs and SG&A expenses

Breakdown by Application (FY26/6 Actual - FY27/6 Plan)

Orders Received

(Unit: ¥1 billion)

	FY26/6					FY27/6
	Q1	Q2	Q3	Q4	Full Year	Plan
Semiconductors and Electronics	18.0	28.7	41.5	25.1	113.3	115.5
▪ Memory	less than 20%	about 20%	more than 30%	about 40%	less than 30%	more than 30%
▪ Logic	more than 30%	mid-30%	less than 40%	several%	less than 30%	mid-20%
▪ Electronics	mid-10%	less than 20%	mid-10%	more than 40%	more than 20%	mid-10%
▪ Power semiconductors	several%	less than 10%	several%	▲ less than 10%	several%	mid-single digits
▪ Packaging	more than 30%	less than 20%	more than 10%	more than 20%	about 20%	about 20%
Display and Energy	13.0	18.3	11.9	23.8	67.0	44.5
▪ LCD	more than 40%	mid-30%	less than 50%	less than 20%	more than 30%	less than 50%
▪ OLED	less than 50%	mid-60%	more than 50%	less than 70%	less than 60%	less than 50%
▪ Other	mid-10%	several%	several%	mid-10%	less than 10%	mid-single digits

Breakdown by Application (FY26/6 Actual - FY27/6 Plan)

Net Sales

(Unit: ¥1 billion)

	FY26/6					FY27/6
	Q1	Q2	Q3	Q4	Full Year	Plan
Semiconductors and Electronics	16.2	21.3	25.6	25.3	88.3	107.0
▪ Memory	less than 30%	more than 20%	less than 20%	mid-10%	less than 20%	mid-20%
▪ Logic	less than 20%	about 30%	less than 30%	less than 40%	less than 30%	less than 30%
▪ Electronics	more than 20%	less than 30%	less than 20%	more than 30%	mid-20%	mid-20%
▪ Power semiconductors	more than 10%	mid-10%	mid-single digits	▲ several%	mid-single digits	several%
▪ Packaging	less than 20%	mid-single digits	more than 30%	about 20%	about 20%	more than 20%
Display and Energy	11.1	19.7	14.7	18.2	63.7	48.5
▪ LCD	more than 30%	less than 40%	about 30%	more than 30%	more than 30%	about 30%
▪ OLED	mid- 60%	less than 60%	mid-60%	less than 70%	more than 60%	about 60%
▪ Other	several%	mid-single digits	mid-single digits	several%	several%	about 10%

Operating profit margin ranking (FY26/6 4Q - Full Year)

Semiconductor business only: 3rd

Rank	Q1	Q2	Q3	Q4	Full Year
1	Components	Industries	Industries	Industries	Industries
2	Industries	Display and Energy-Related	Components	Others	Components
3	Display and Energy-Related	Components	Display and Energy-Related	Components	Others
4	Others	Semiconductors and Electronics	Others	Materials	Display and Energy-Related
5	Materials	Others	Semiconductors and Electronics*	Display and Energy-Related	Materials
6	Semiconductors and Electronics	Materials	Materials	Semiconductors and Electronics *	Semiconductors and Electronics *

Overall average OPM

* Profitability declined due to one-off EV-related factors in the Semiconductor & Electronics segment.

- ❑ **PVD (Physical Vapor Deposition)**
A thin-film deposition technology, primarily sputtering for ULVAC.
- ❑ **MHM (Metal Hard Mask)**
A mask film used in etching processes for wiring layer formation. (Sputtering for ULVAC)
- ❑ **FEOL (Front End of Line)**
The initial stage of semiconductor manufacturing, forming transistors and other components on silicon wafers.
- ❑ **BEOL (Back End of Line)**
Refers to the latter stage of the semiconductor manufacturing process, where wiring and metal layers are formed to connect devices such as transistors created during the FEOL (Front End of Line) process.
- ❑ **GPU (Graphics Processing Unit)**
A processor designed for high-speed rendering of images and videos. It is also suitable for repetitive calculations, such as addition, subtraction, multiplication, and division, in AI inference.
- ❑ **HBM (High Bandwidth Memory)**
A next-generation memory technology that stacks multiple DRAMs vertically for high speed and density.
- ❑ **WLP (Wafer Level Package)**
A semiconductor packaging technology performed at the wafer level.
- ❑ **PLP (Panel Level Package)**
A packaging technology using panel-shaped substrates instead of wafers.
- ❑ **POR (Process of Record)**
A certified process used in mass production.
- ❑ **HM (Hard Mask)**
A mask layer formed using PVD (Physical Vapor Deposition) or similar methods.

**技術屋は、
世界が変わる
場所にいる。**

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